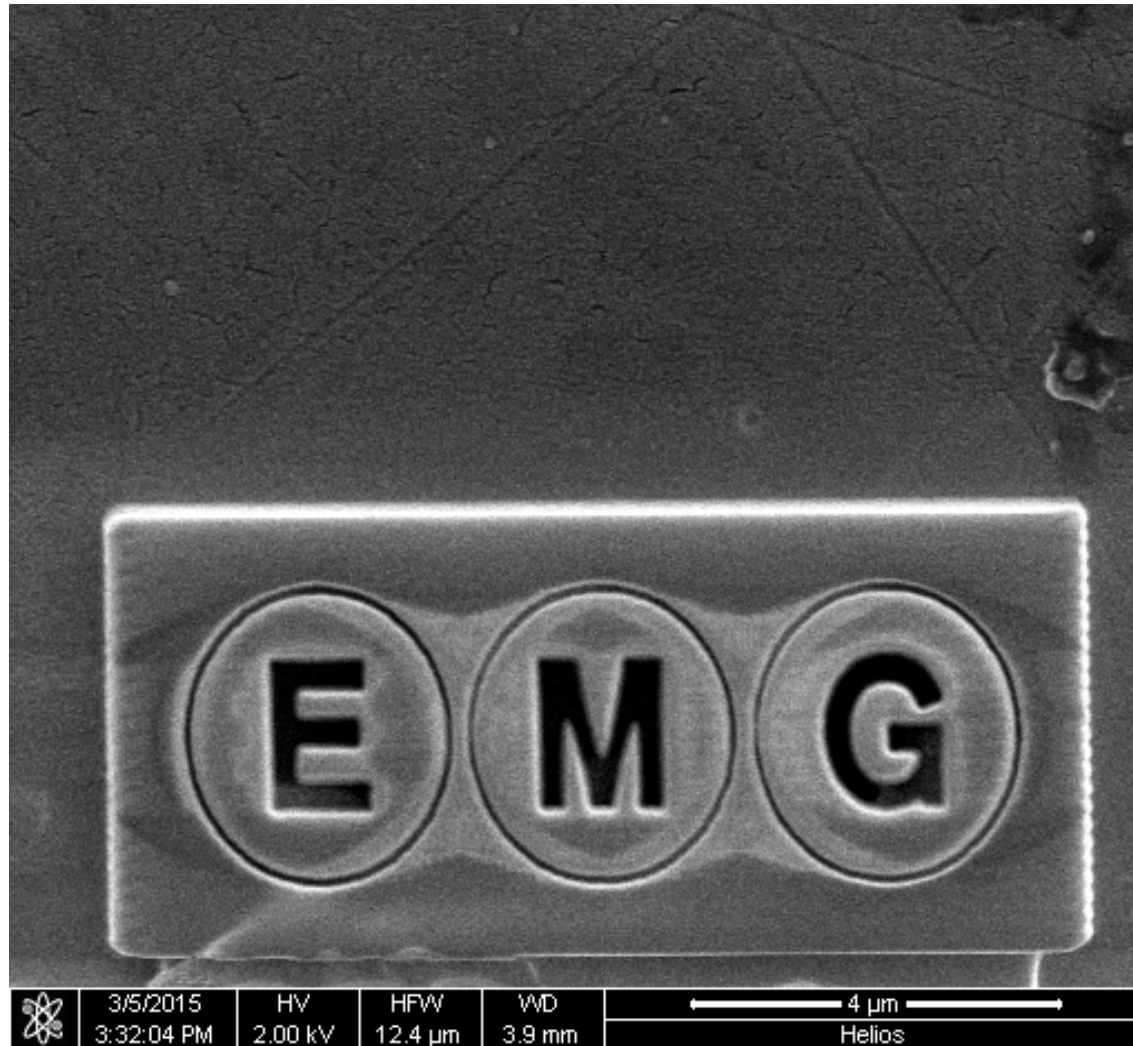


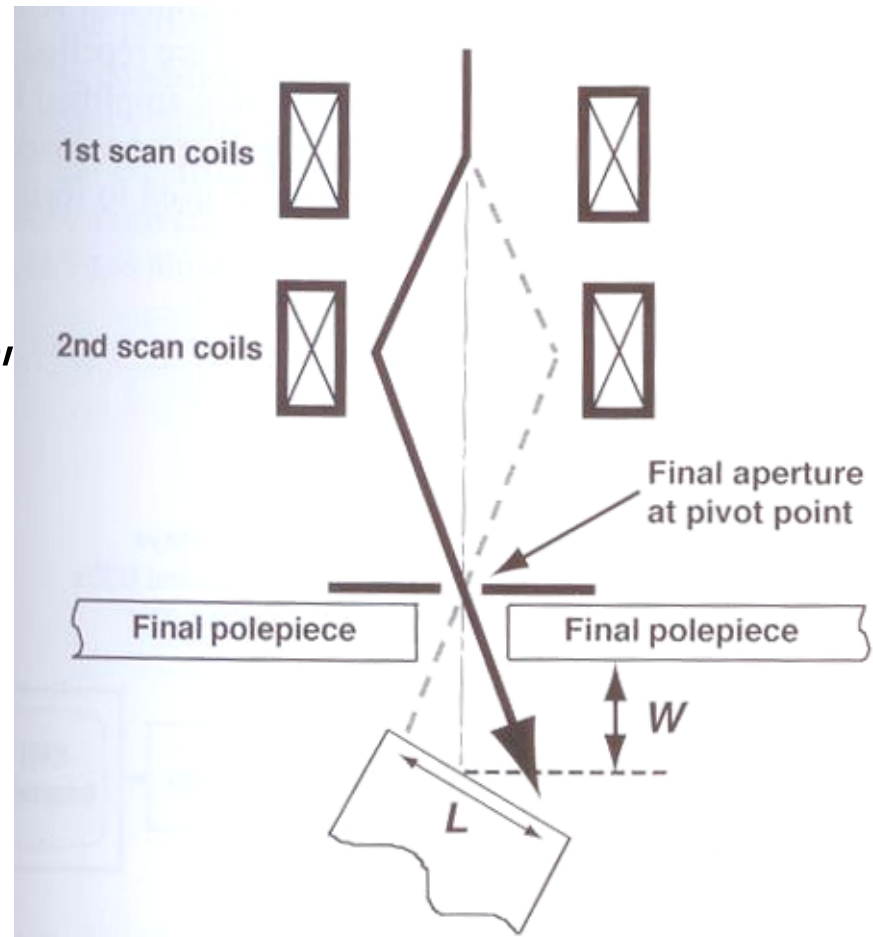
FIB/SEM

Feb. 13, 2017



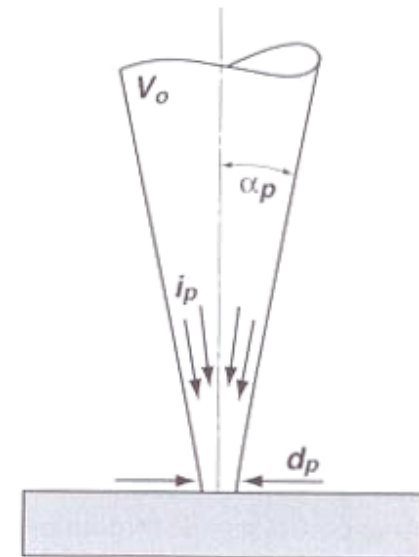
SEM Basics

- ◆ Electron probe is focused to a sharp point
- ◆ The probe is scanned across the specimen point by point, with each point producing signal
- ◆ Scan coils deflect beam to move across sample



SEM Beam: probe size

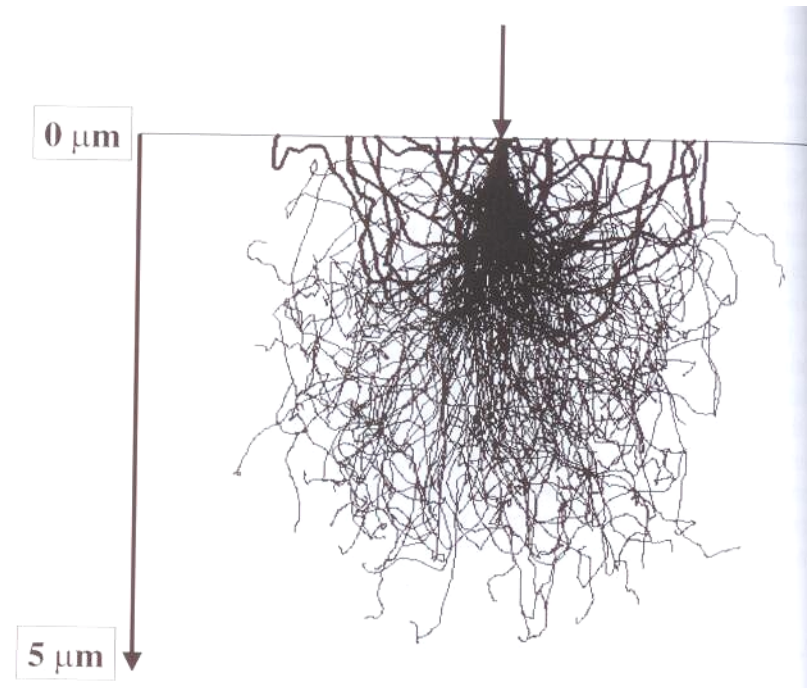
- ◆ Ideally want as small a probe as possible, relative to pixel size
- ◆ Probe size is determined by voltage, current, divergence angle
- ◆ Lens distortions
 - ◆ Spherical aberration (focus different at center and edge of lens) – instrument dependent
 - ◆ Aperture diffraction
 - ◆ Astigmatism (user correctable)
 - ◆ Chromatic aberration – voltage dependent



Goldstein et al, 2003

Beam-Specimen Interaction

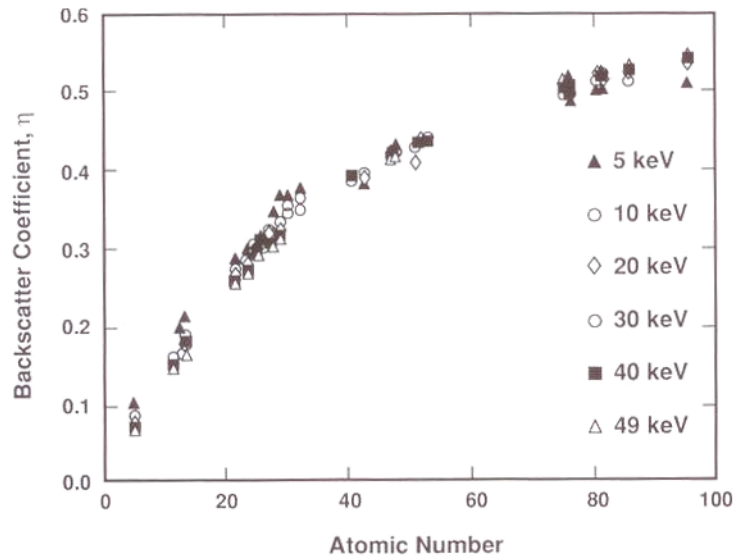
- Monte Carlo simulation of a 20 keV beam in Si
 - Dark traces: electrons which left the sample (BSE's)
- Electrons may be scattered elastically or inelastically
- Probability of elastic scattering $\sim Z^2$
- Inelastic scattering:
 - Secondary electrons
 - X-rays



BSE's and SE's

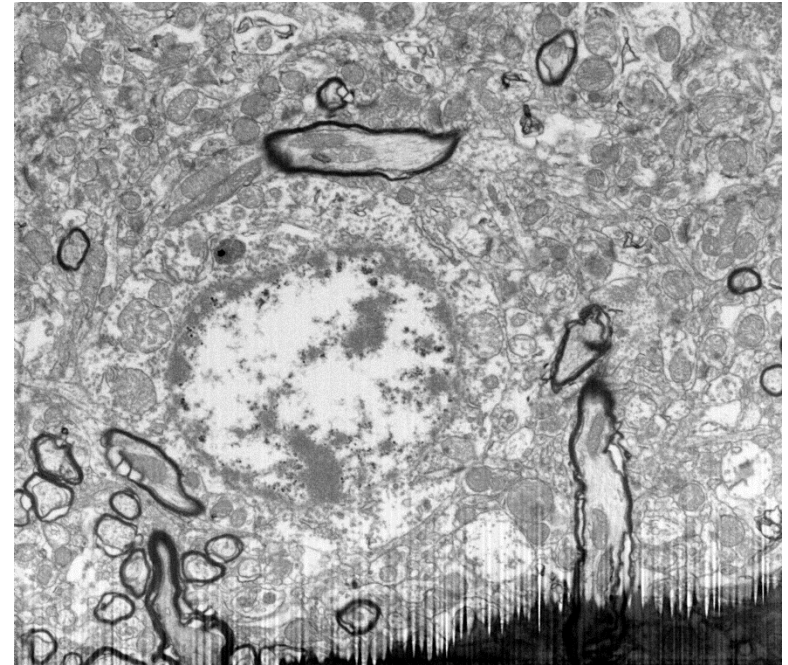
BSE efficiency is material dependent, voltage independent

Fraction of
e's that backscatter

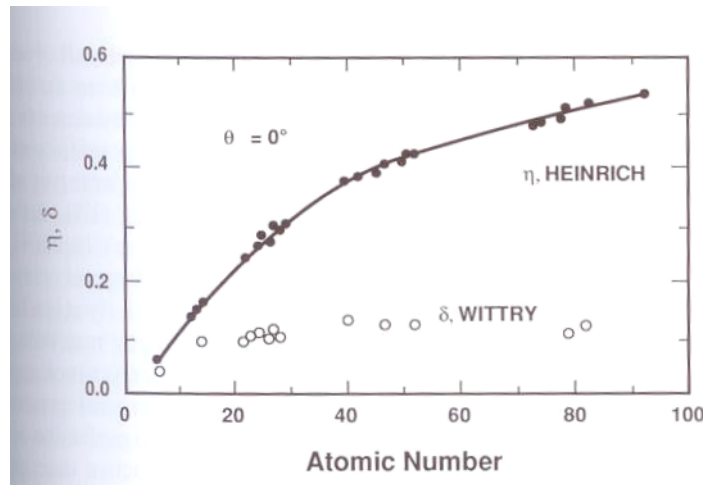


Goldstein et al, 2003

BSE's give contrast between
light and heavy elements



Specimen Dependence of BSE, SE

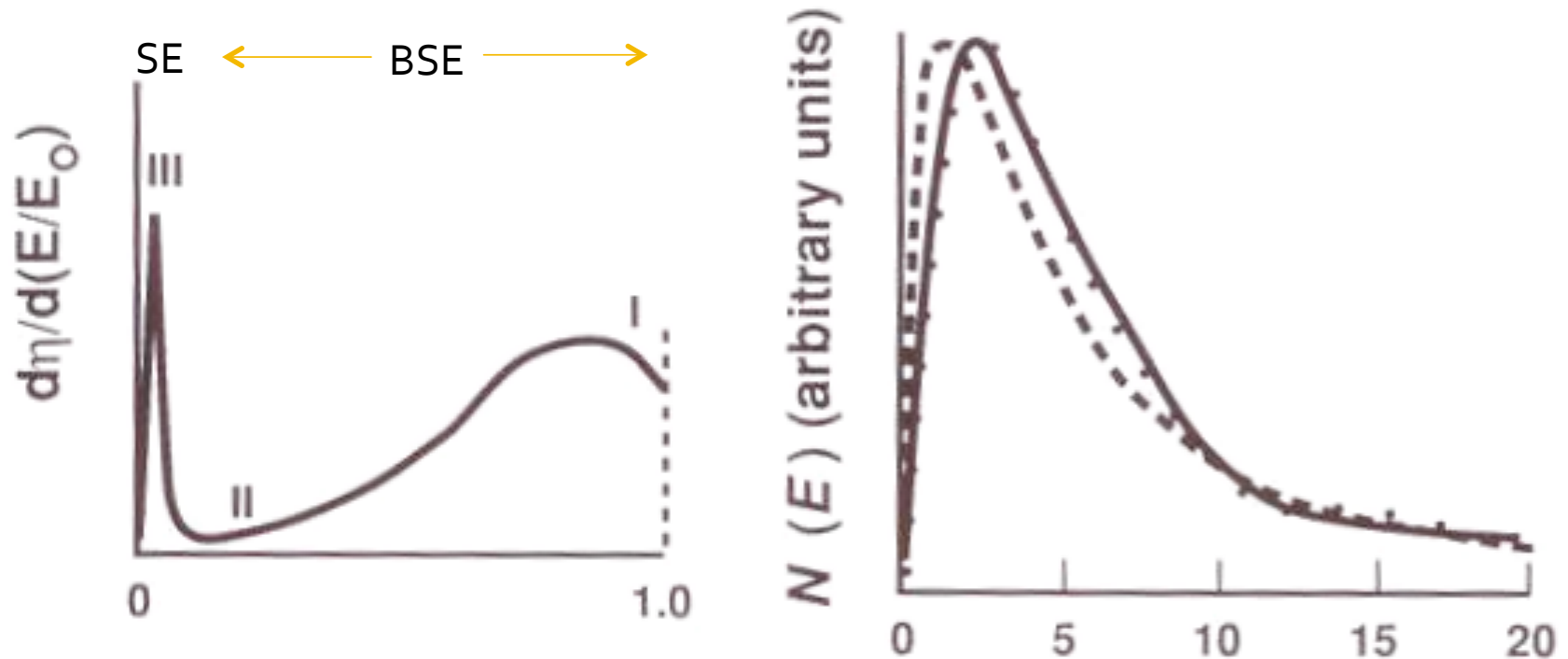


30 keV

SE's are less sensitive to atomic number than BSE's
(may be more sensitive at lower beam energies)

Goldstein et al, 2003

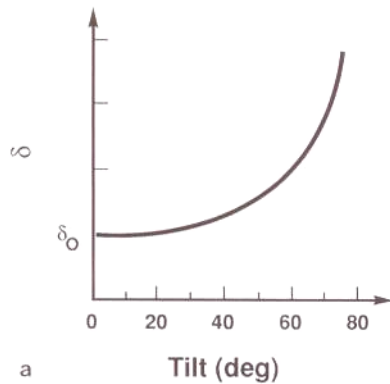
Energies of SE and BSE



SE's have much lower energy (majority < 20 eV)

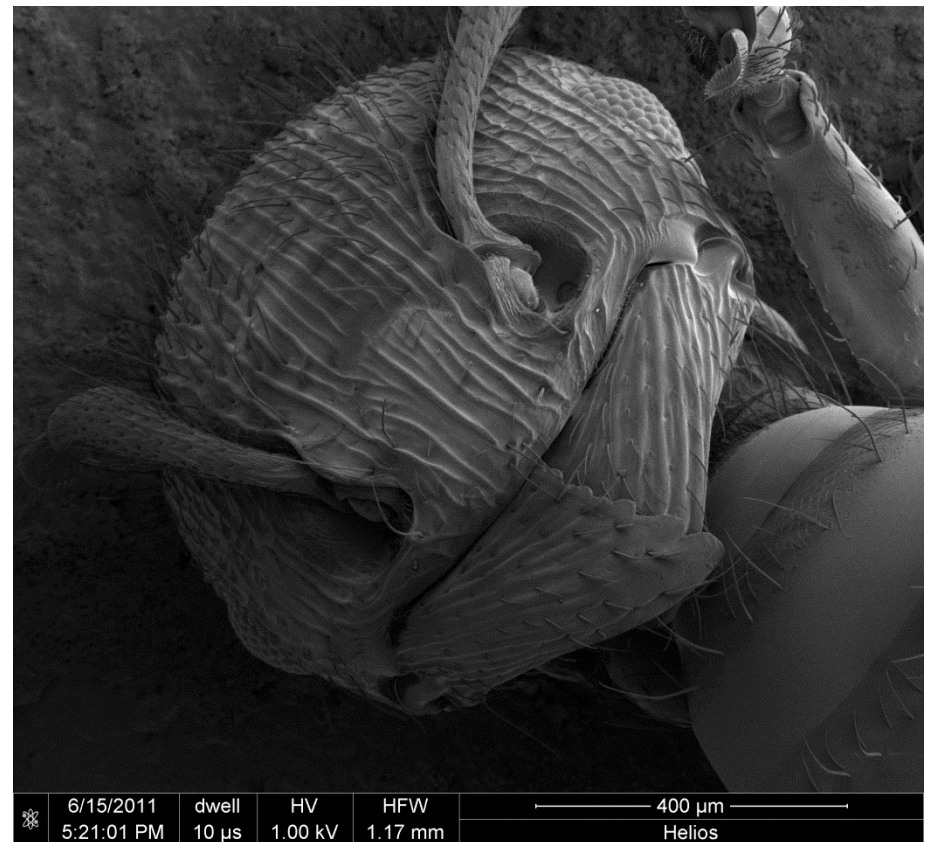
Goldstein et al, 2003

Angular Dependence of SE's



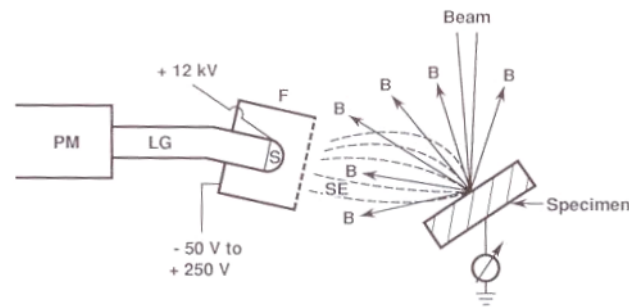
Goldstein et al, 2003

SE's also give topographic information



Detection of BSE's, SE's

Everhart-Thornley (ET) Detector



Electrons strike scintillator, releasing photons

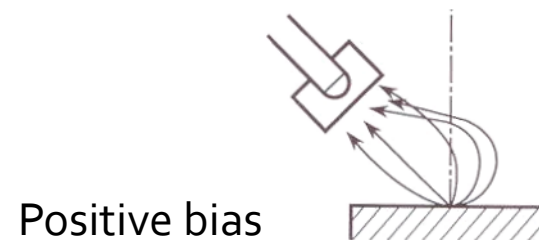
Photons travel to photomultiplier tube

Eventually converted to electric signal, storing intensity values

Combined SE/BSE detector

Apply bias

- ◆ Bias can be applied to detector, directing electrons toward or away from it
 - ◆ Negative bias (< -50 V): detect only BSE's
 - ◆ Positive bias: collect more SE's, indirect BSE's : greater total signal



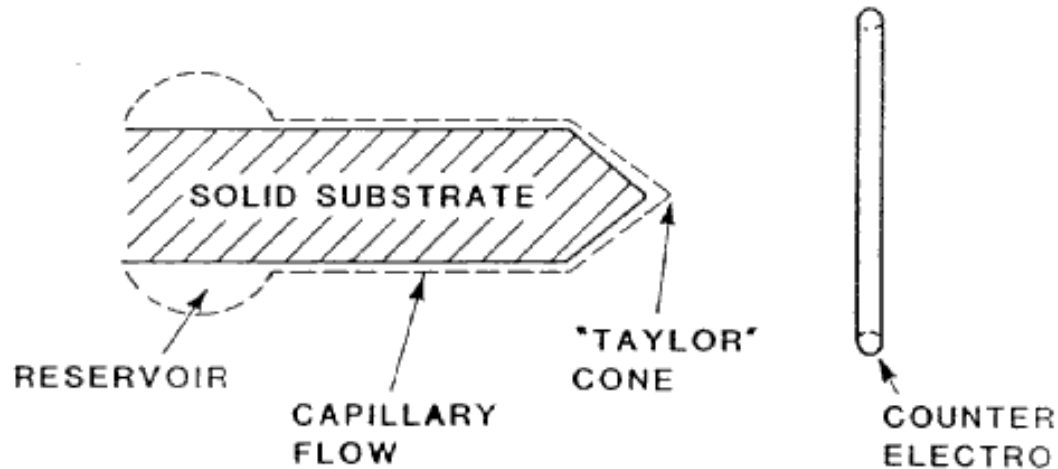
SEM summary

- Images formed by scanning points across sample
- For higher resolution, want to minimize both probe size and interaction volume
 - Low voltage operation
 - But still need enough signal for detection
- Use Through-lens detector for higher resolution imaging
- Apply negative bias to detect mainly BSE's

FIB Operation

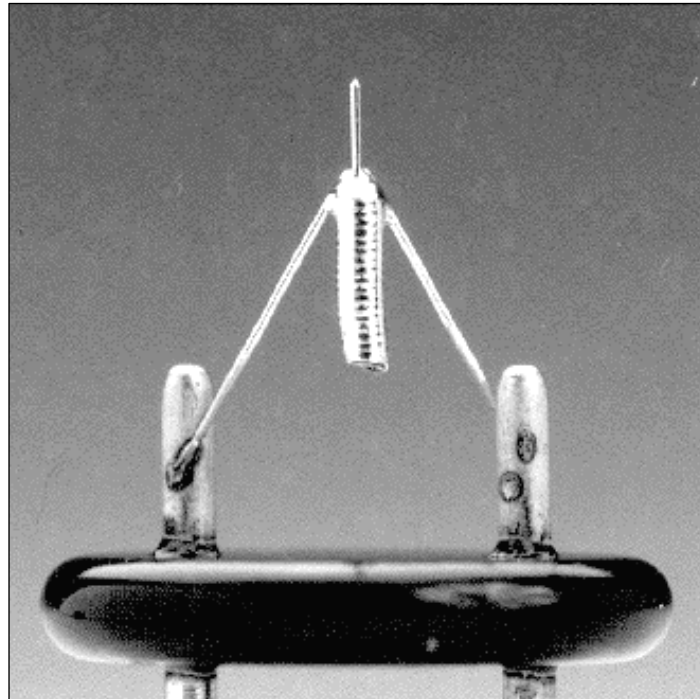
Basic Mechanism

- ◆ Liquid Flow from Reservoir
- ◆ Ion Formation
- ◆ External Beam Interactions



Gallium is the Most Popular LMIS

- ◆ A liquid metal
- ◆ Room temperature operation
- ◆ Long lived (500-1500 hr sources)
- ◆ High vacuum compatible
- ◆ Large ion for sputtering

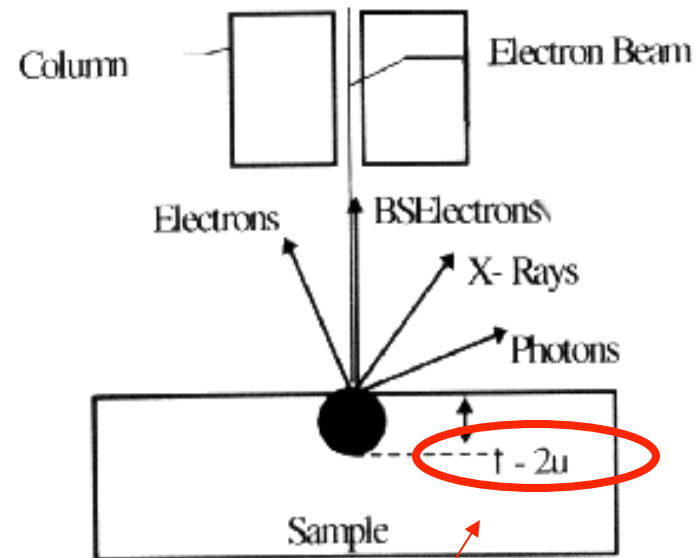
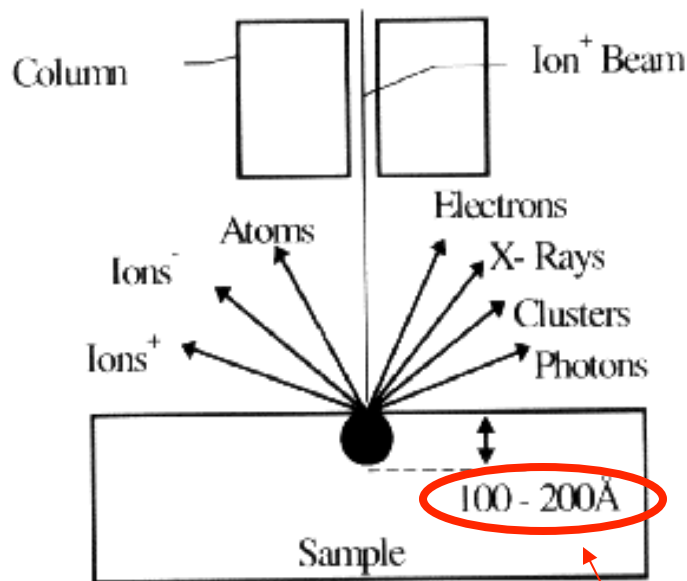


Ion Column

- ◆ Source - LMIS at top
- ◆ Focusing Optics
 - Use Electrostatic lenses since ions are heavier than electrons.
- ◆ Deflection Electronics/Pattern Board
- ◆ High-speed Blanking
 - Need to prevent milling while blanking

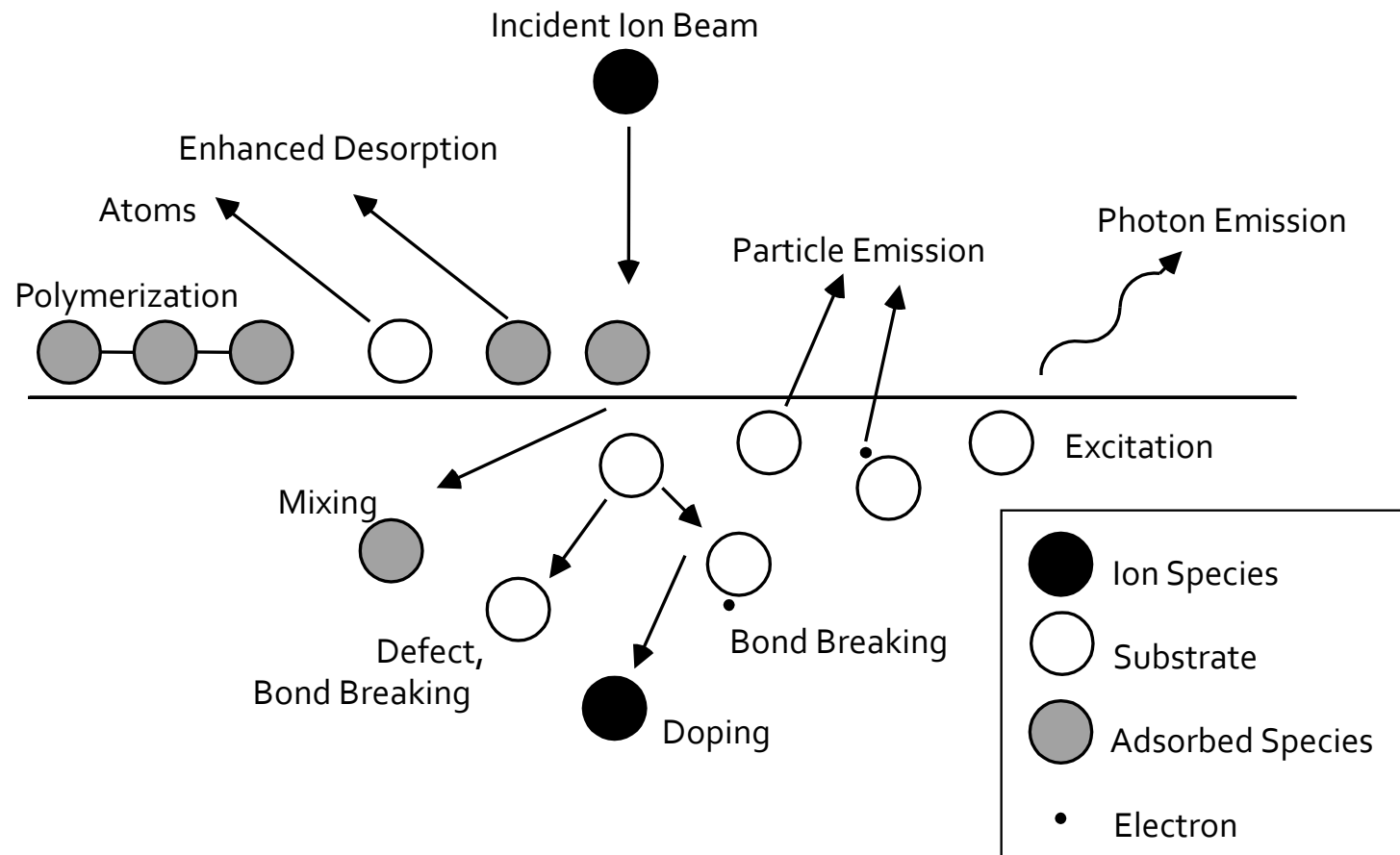
Using the System

◆ Beam Interactions



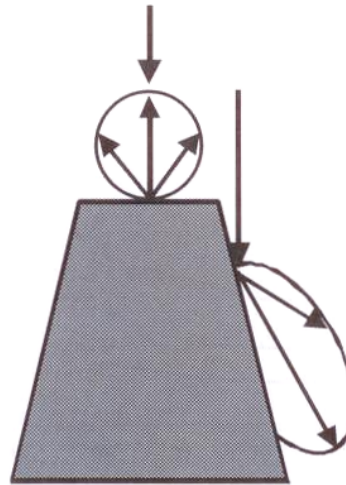
Note difference in interaction volume

Ion Beam to Sample Interactions

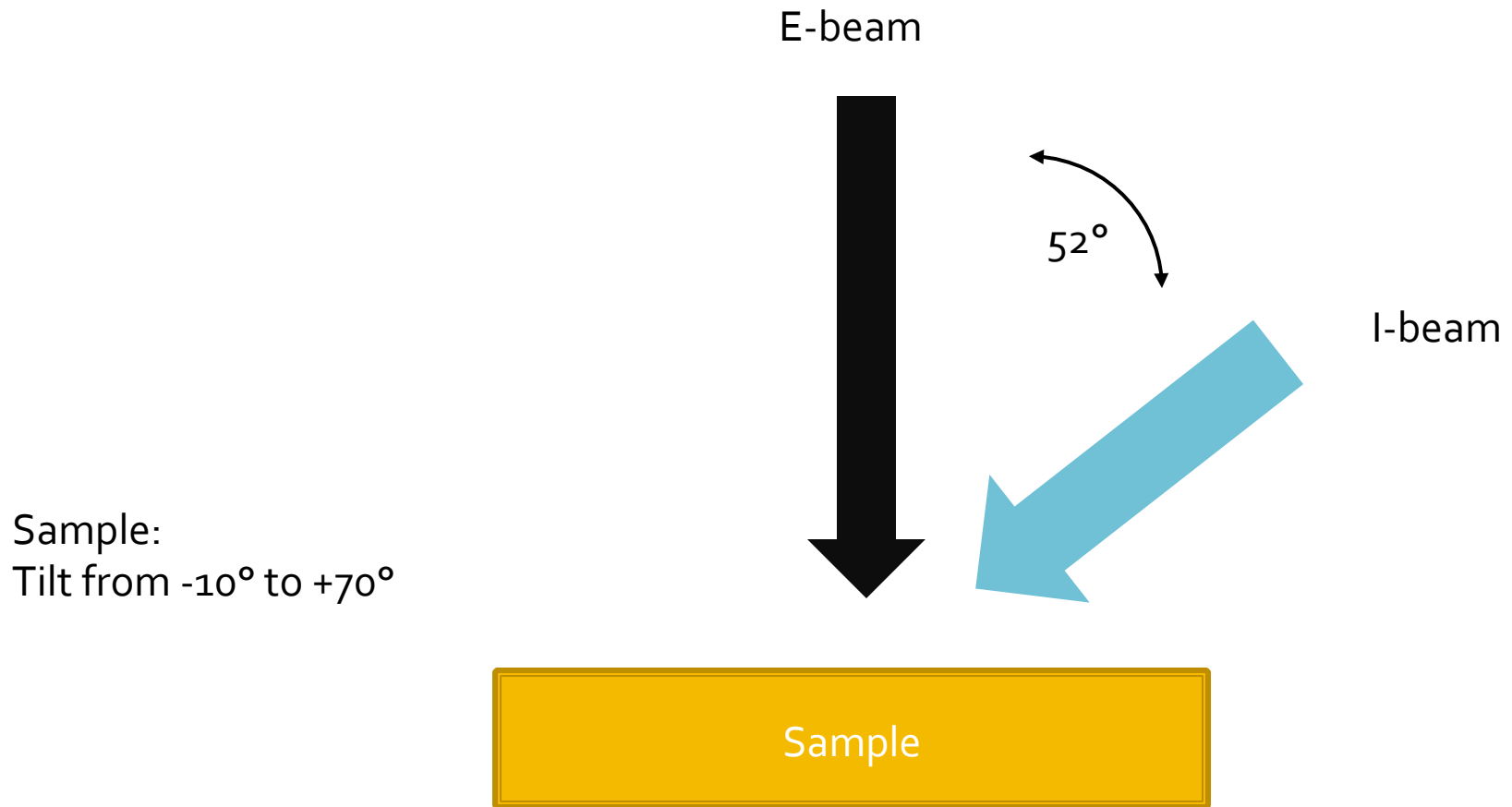


Sputtered Particles

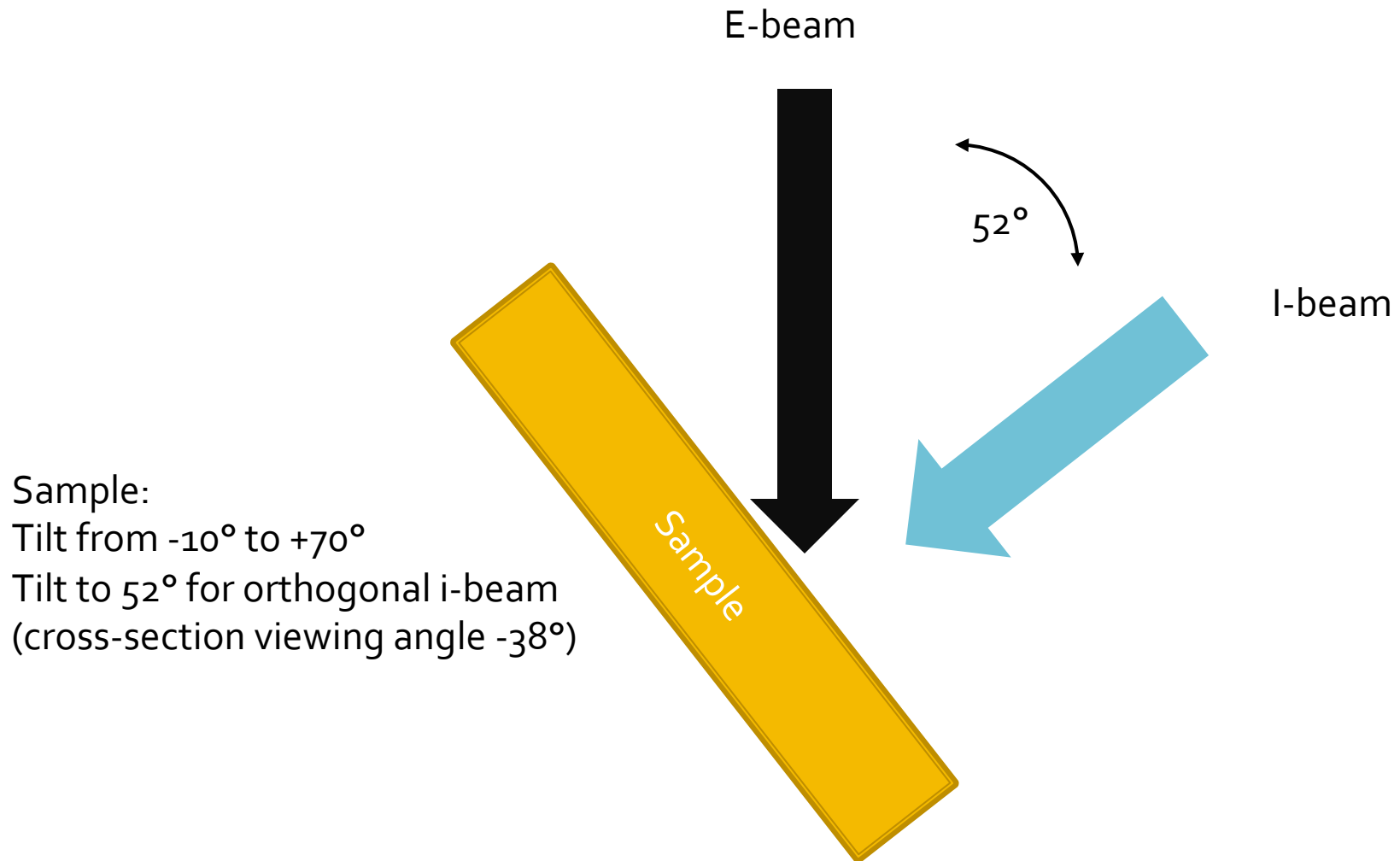
Sputtered Particle Ejection Behavior



Geometry

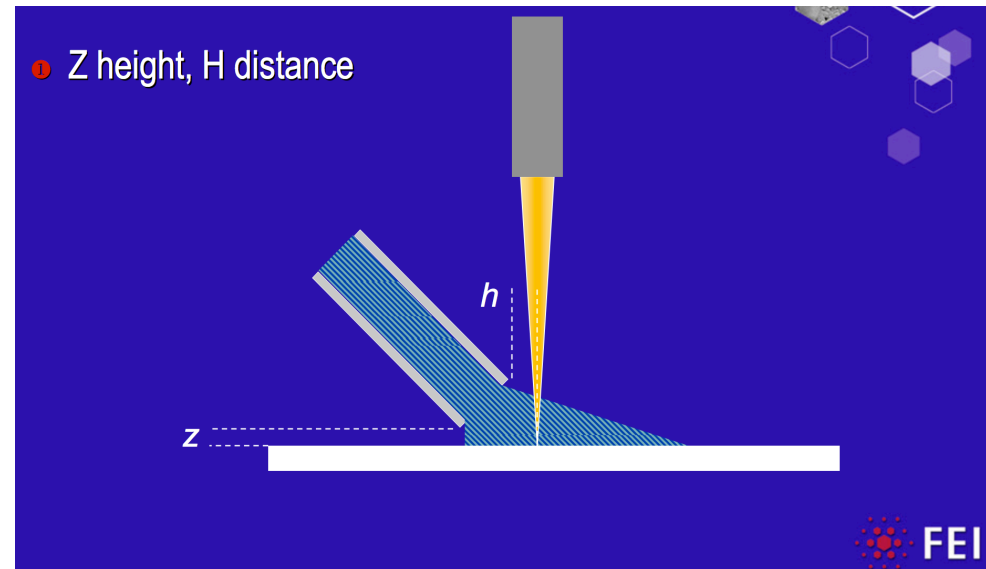


Geometry



Deposition

- (Methylcyclopentadienyl) trimethyl platinum
- Warm to gas, spray over sample with needle
- I-beam or e-beam interactions break it apart, deposit metal onto sample
 - Protection
 - Hard surface for mill



Applications to Resin- embedded tissue

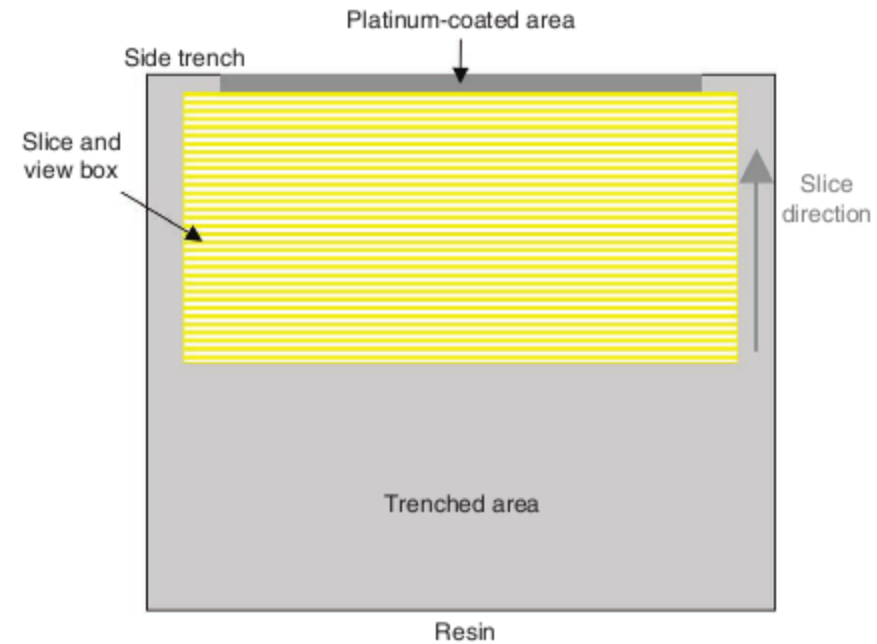
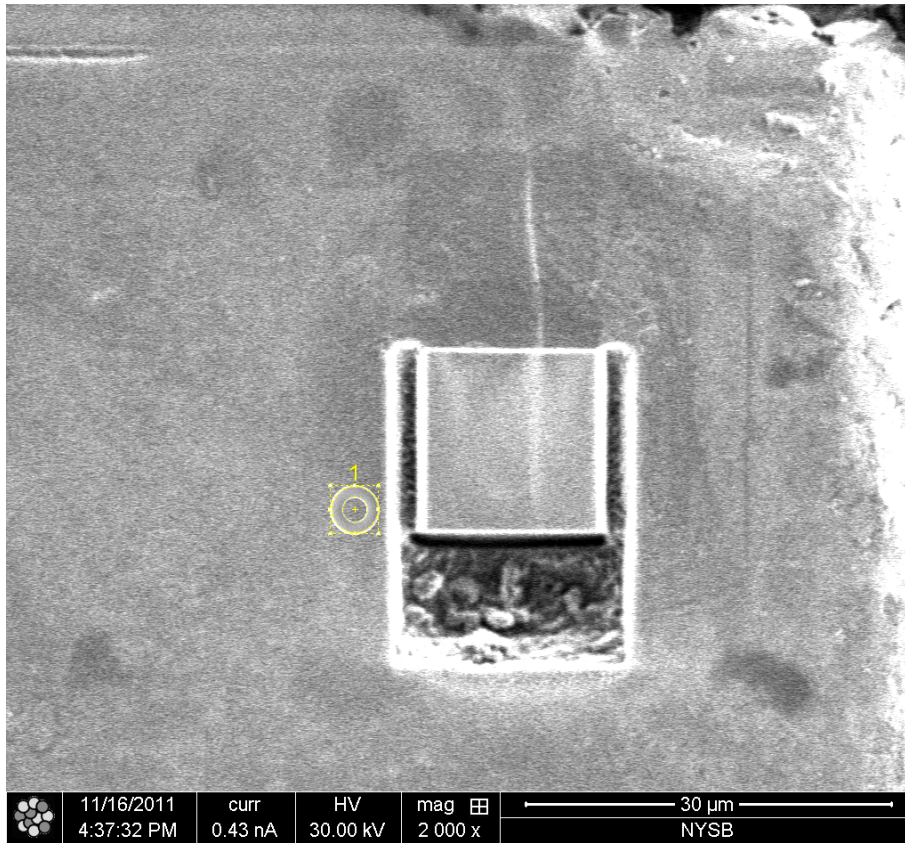
Tissue or Cells

- Sample Prep
 - High Pressure frozen (optional)
 - Chemically fixed, freeze substituted
 - Resin embedded
 - En bloc staining
 - OsO_4 , U Ac, Pb citrate
 - Osmium impregnation (OTO)
 - Want to make samples more conductive, more heavily stained
 - Thin conductive layer (C, Pt, Au-Pd) coated just before insertion

Imaging conditions

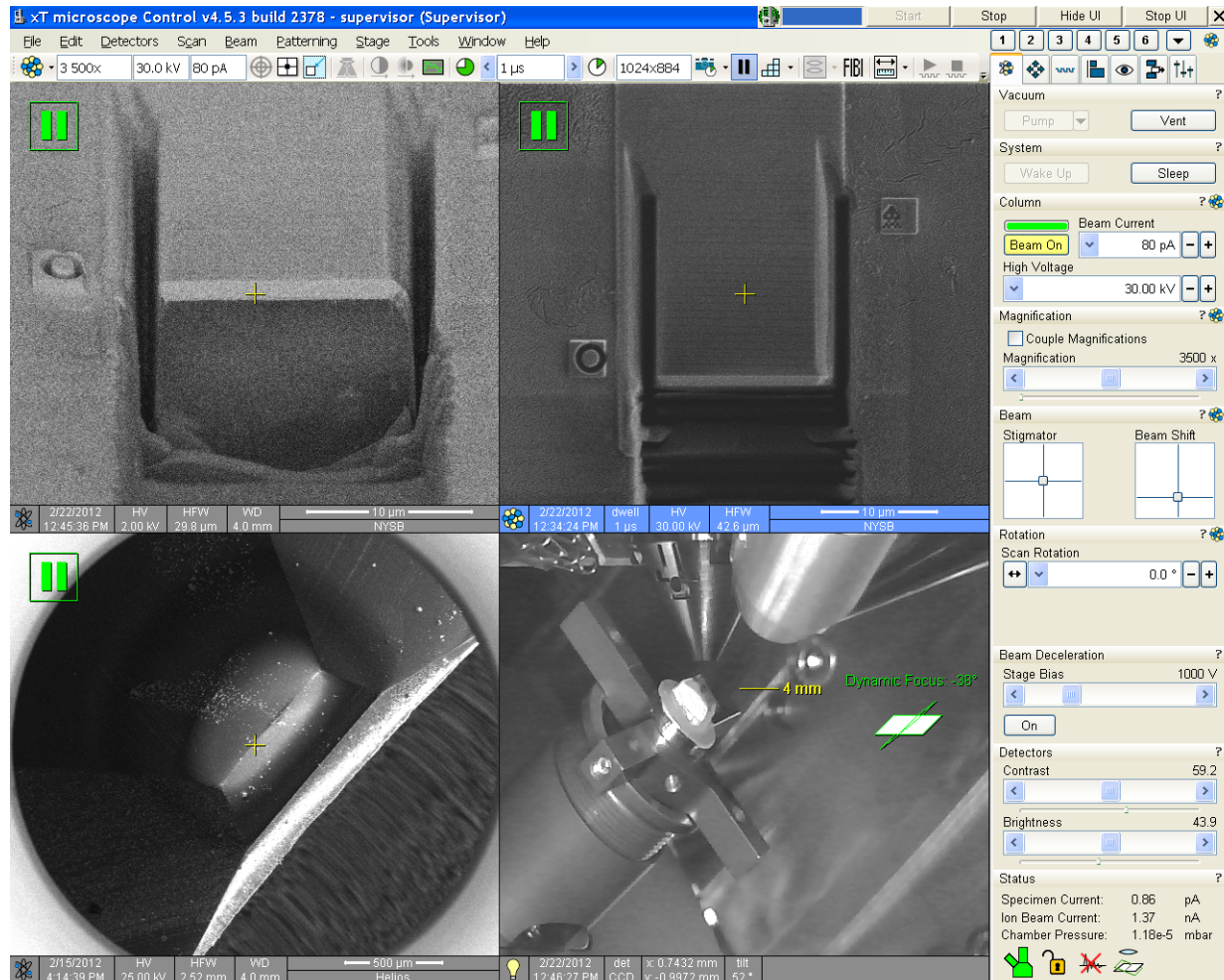
- Low voltage (2 keV or less)
 - Want to image only the surface
 - Minimal depth penetration (slice as thin as 10 nm)
 - No topographic information
 - Elemental contrast (C vs Os)
 - Through-lens detector for highest resolution
 - BSE mode (positive bias)
 - Stained parts will show up as bright on dark

Milling Samples

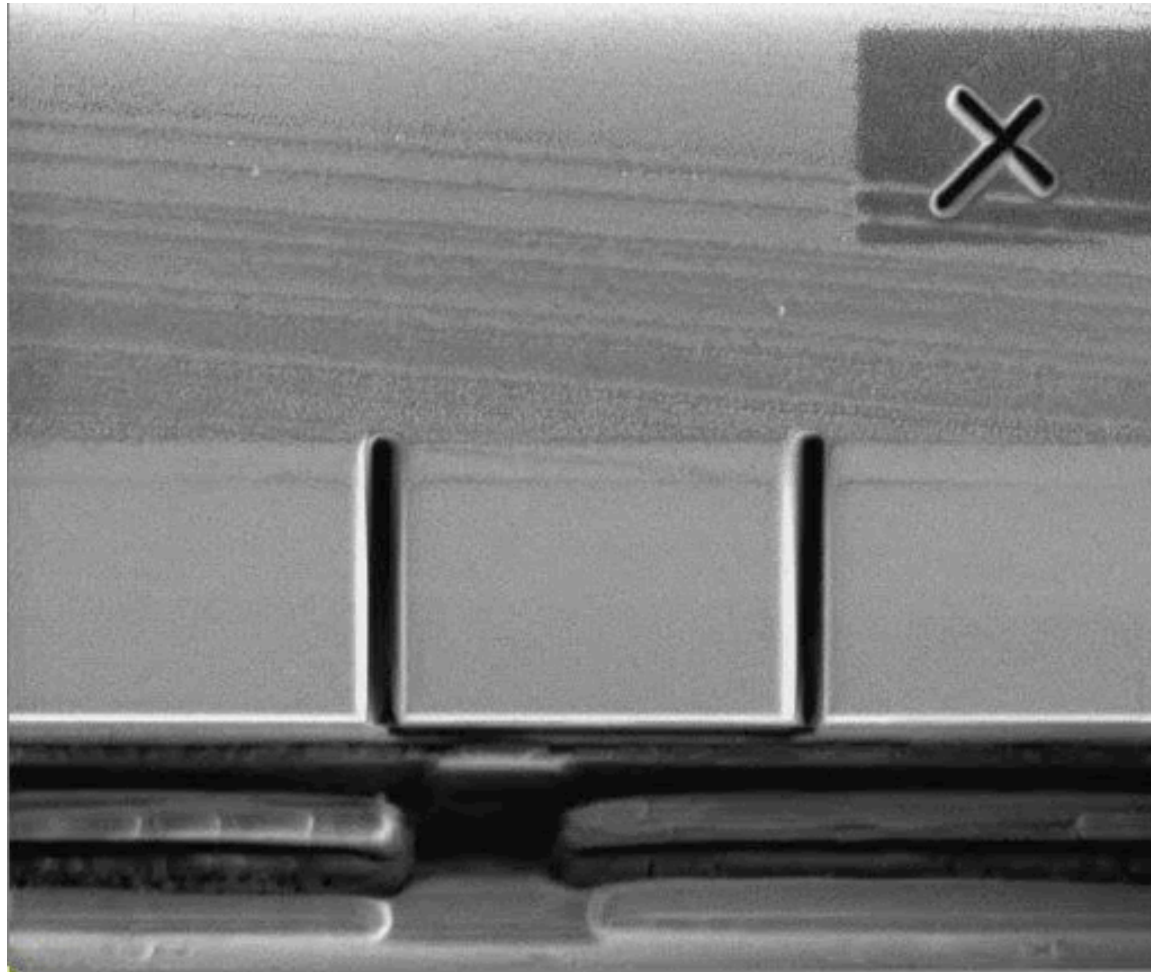


Bushby et al, 2011

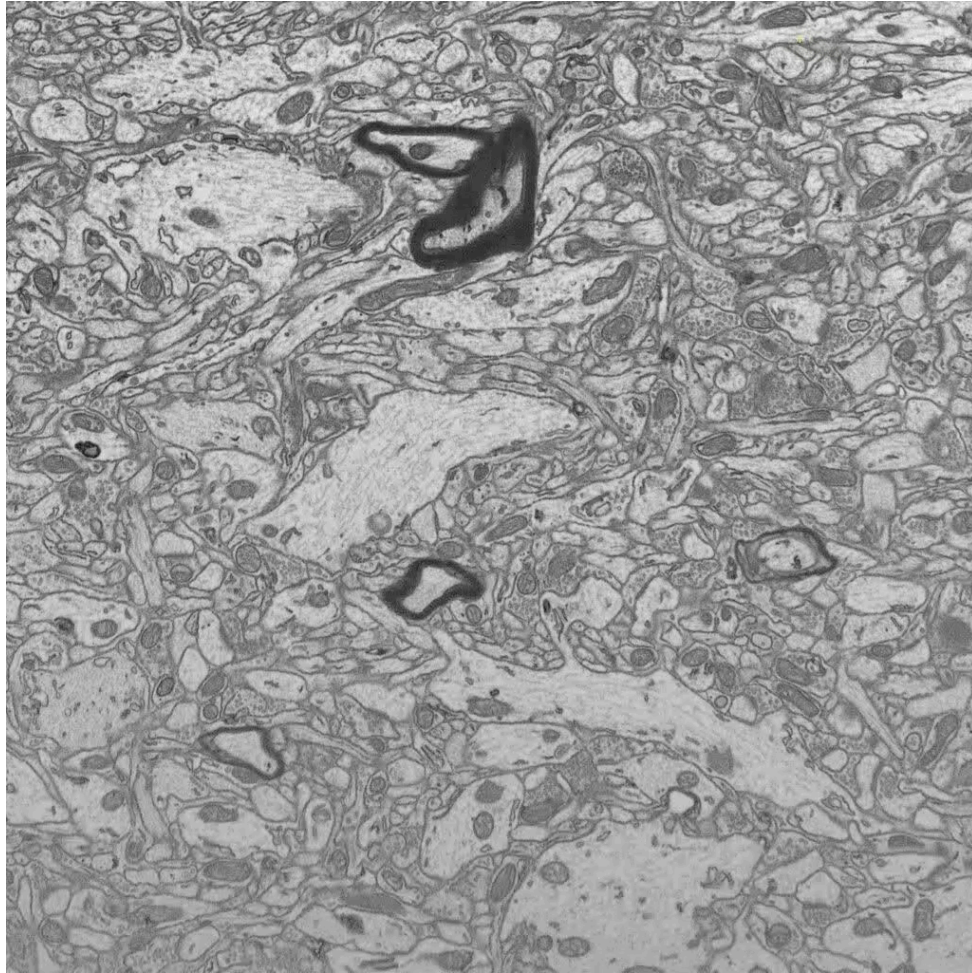
Set up for Slice and View



Milling: i-beam view



Example Movie: Neural Tissue

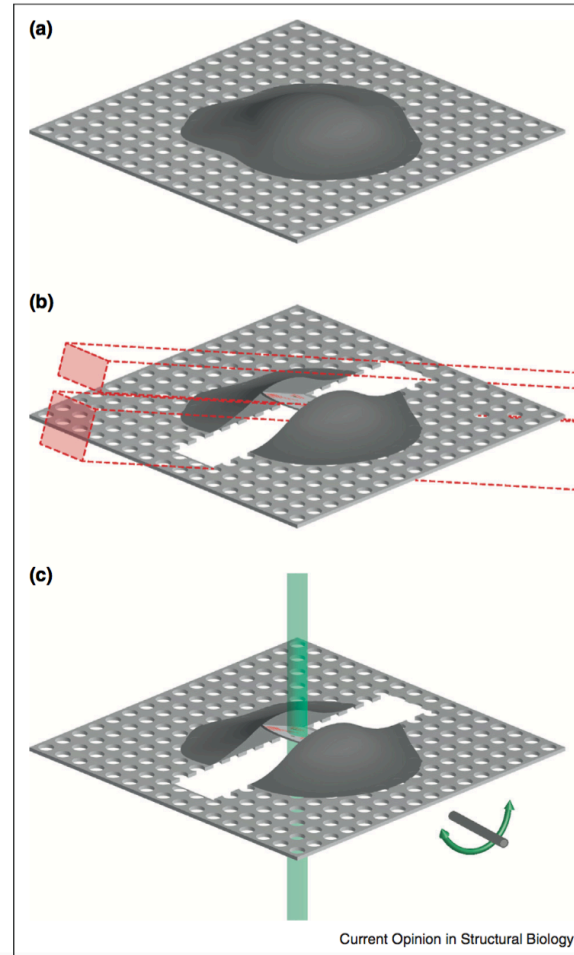


Ideal workflow

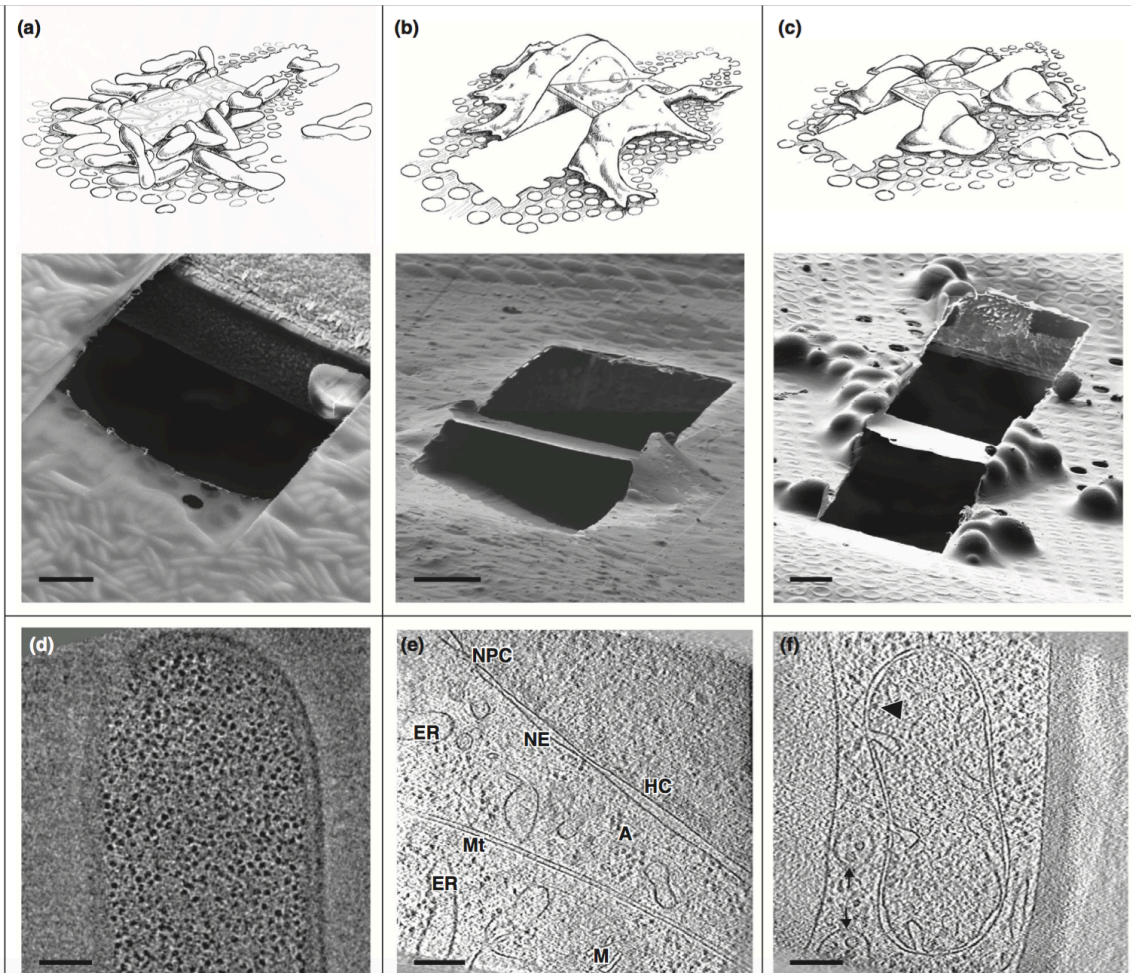
- Samples stained and embedded
- Thin slice for overall map – make easier to find features (LM or ultrathin EM)
- Face of block polished
- Set up for slice and view (1 day)
- Collect slices (1-5 days)
- Align, process (IMOD, Amira) (1 day)
- Segmentation (IMOD, Amira) (weeks-months)

FIB/SEM for Cryo Prep

Mill a thin slice through a cell



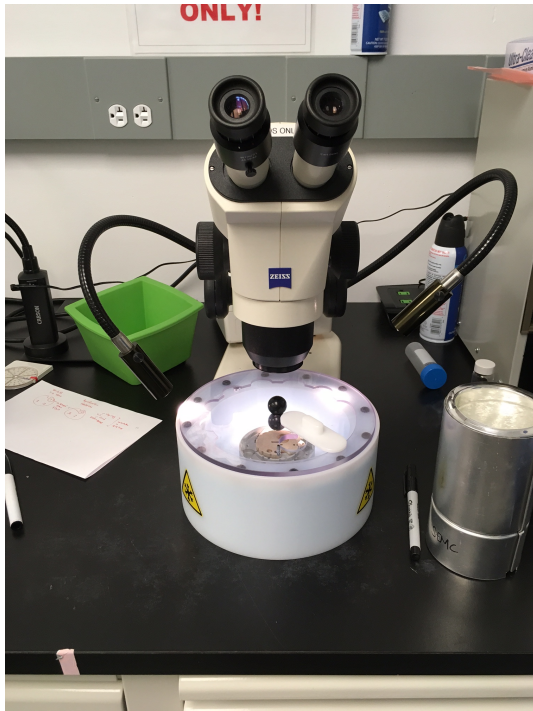
1: Villa E, Schaffer M, Plitzko JM, Baumeister W. Opening windows into the cell: focused-ion-beam milling for cryo-electron tomography. *Curr Opin Struct Biol.* 2013 Oct;23(5):771-7. doi: 10.1016/j.sbi.2013.08.006. Review. PubMed PMID: 24090931.



1: Villa E, Schaffer M, Plitzko JM, Baumeister W. Opening windows into the cell: focused-ion-beam milling for cryo-electron tomography. *Curr Opin Struct Biol.* 2013 Oct;23(5):771-7. doi: 10.1016/j.sbi.2013.08.006. Review. PubMed PMID: 24090931.

Setup for standard Lamellae Preparation

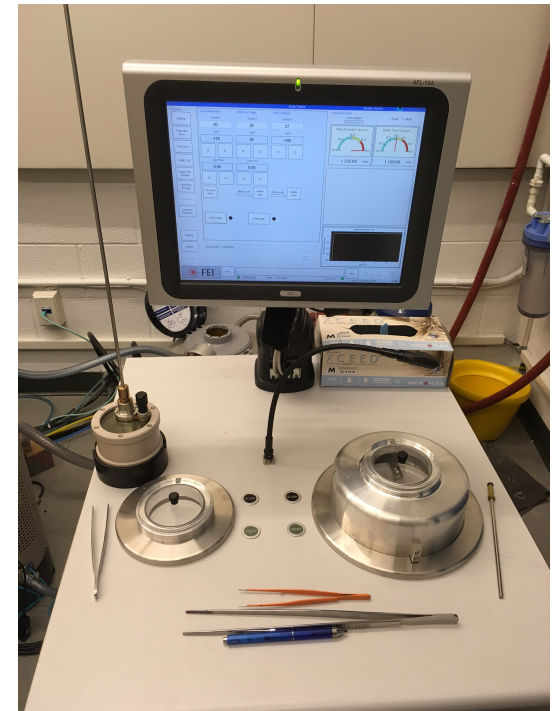
FEI autogrid loading station with stereo microscope



Shuttle with 2 grids

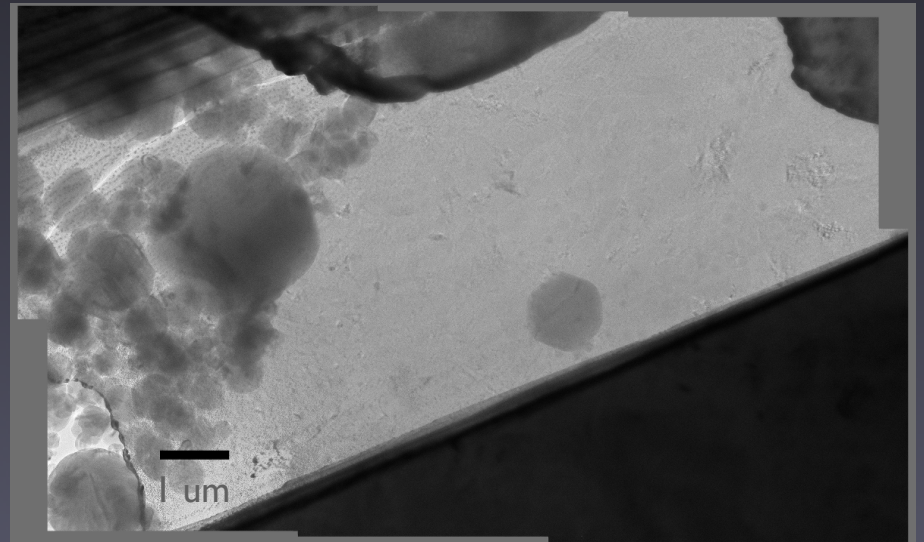
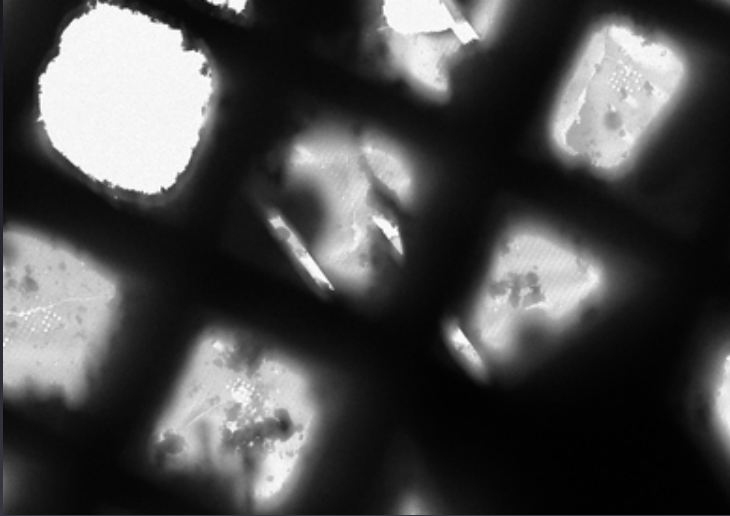


Quorum cryo loading station



Cutting windows into cells and tissues

Find lamella in TEM



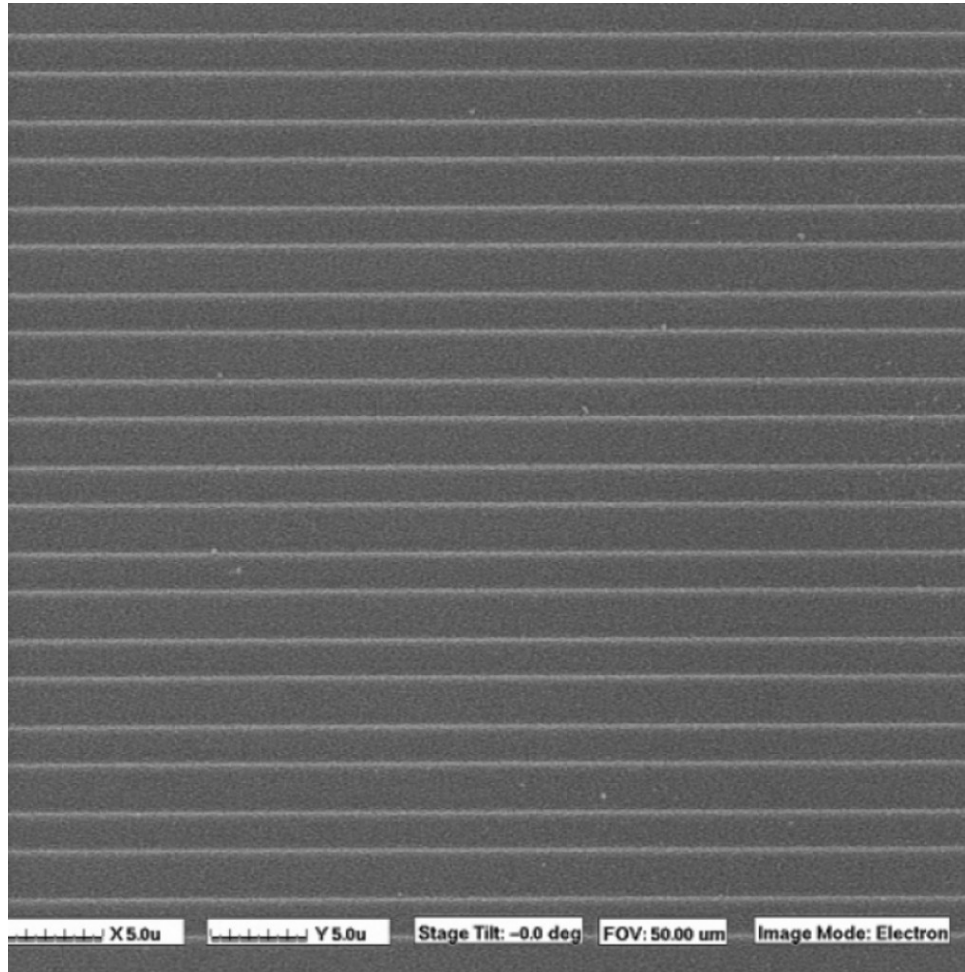
Ideal workflow

- Cells grown on gold grid, then plunge frozen
- Image by cryo-LM to find features (1 day)
- Load into FIB/SEM, mill slices (1 day)
- Load into TEM, collect tomograms (1-2 days)
- Align, process (Protomo, IMOD) (1 day)
- Segmentation (IMOD, Amira)
- Sub-tomogram averaging

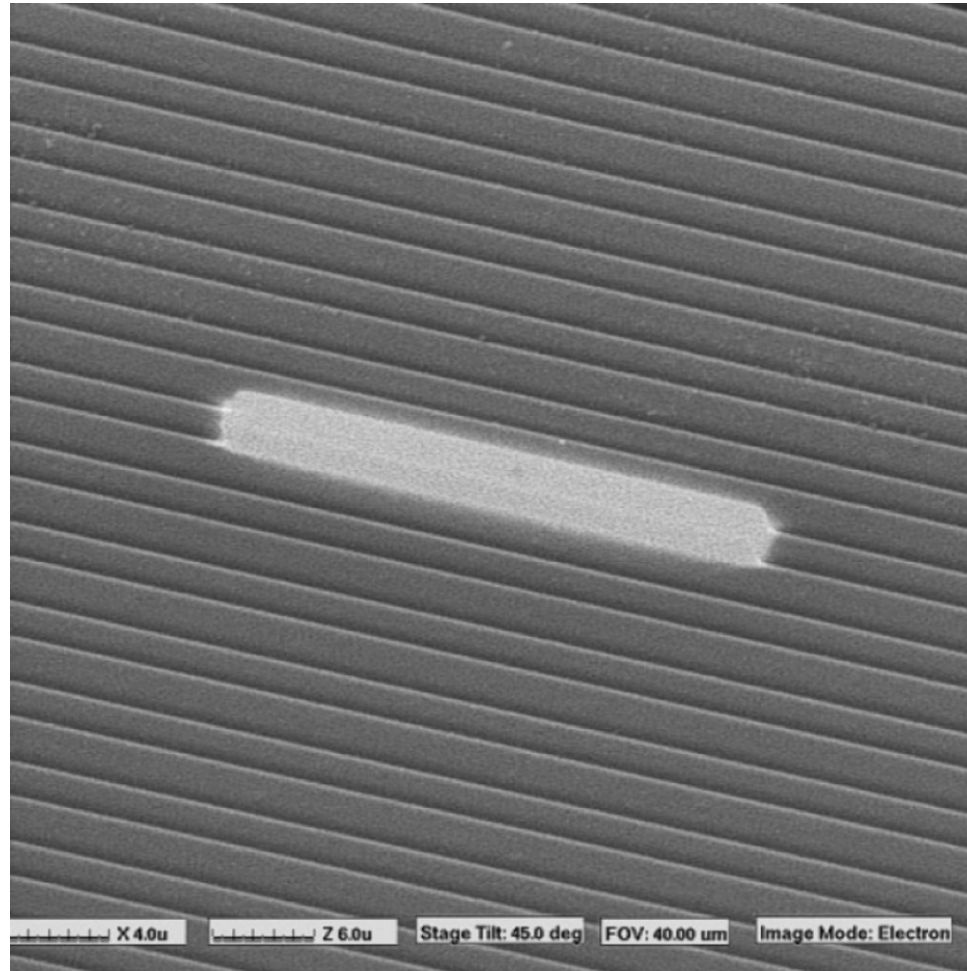
Lift Out

Use of FIB/SEM to prepare bulk material for TEM imaging

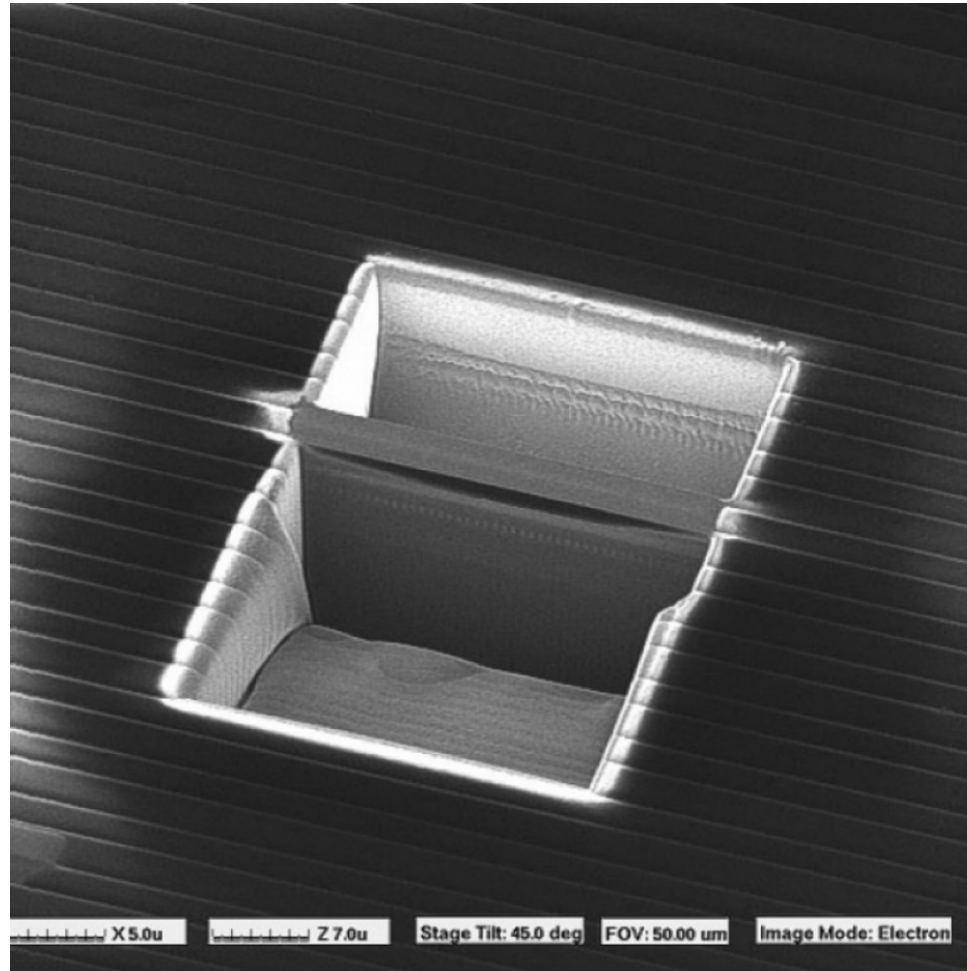
Area of Interest



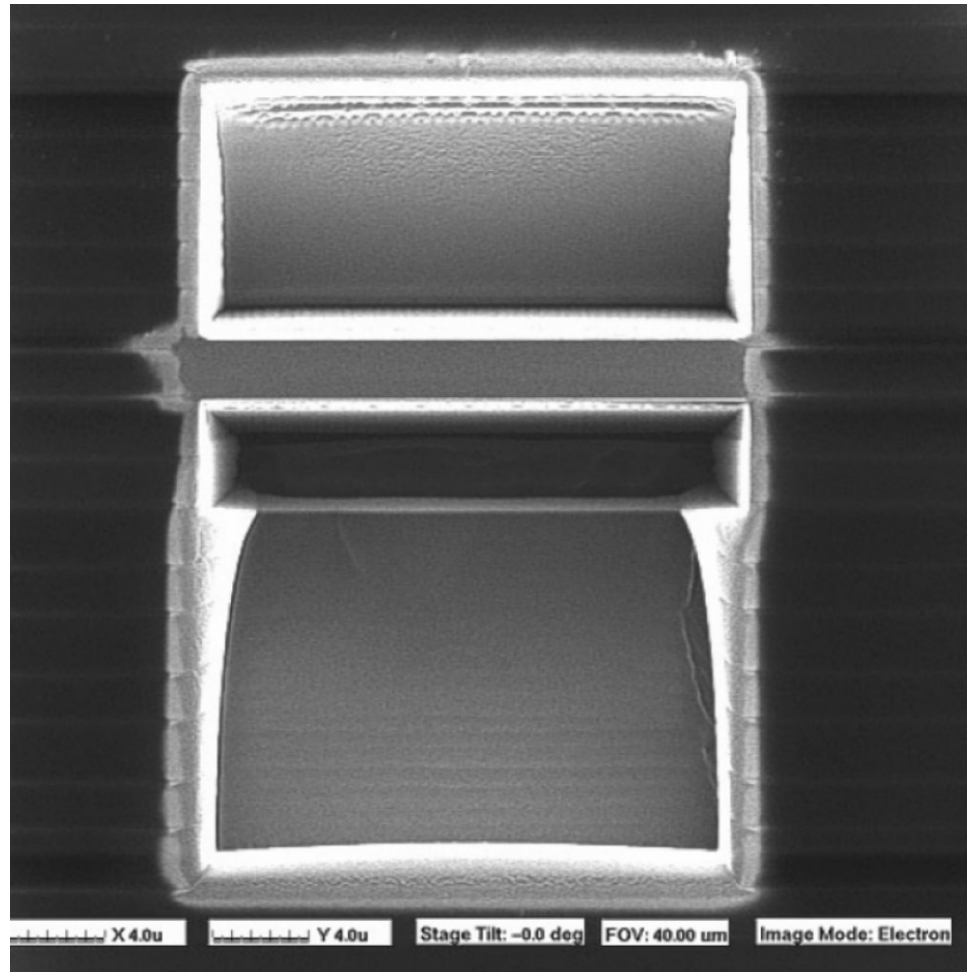
Protect Area of Interest



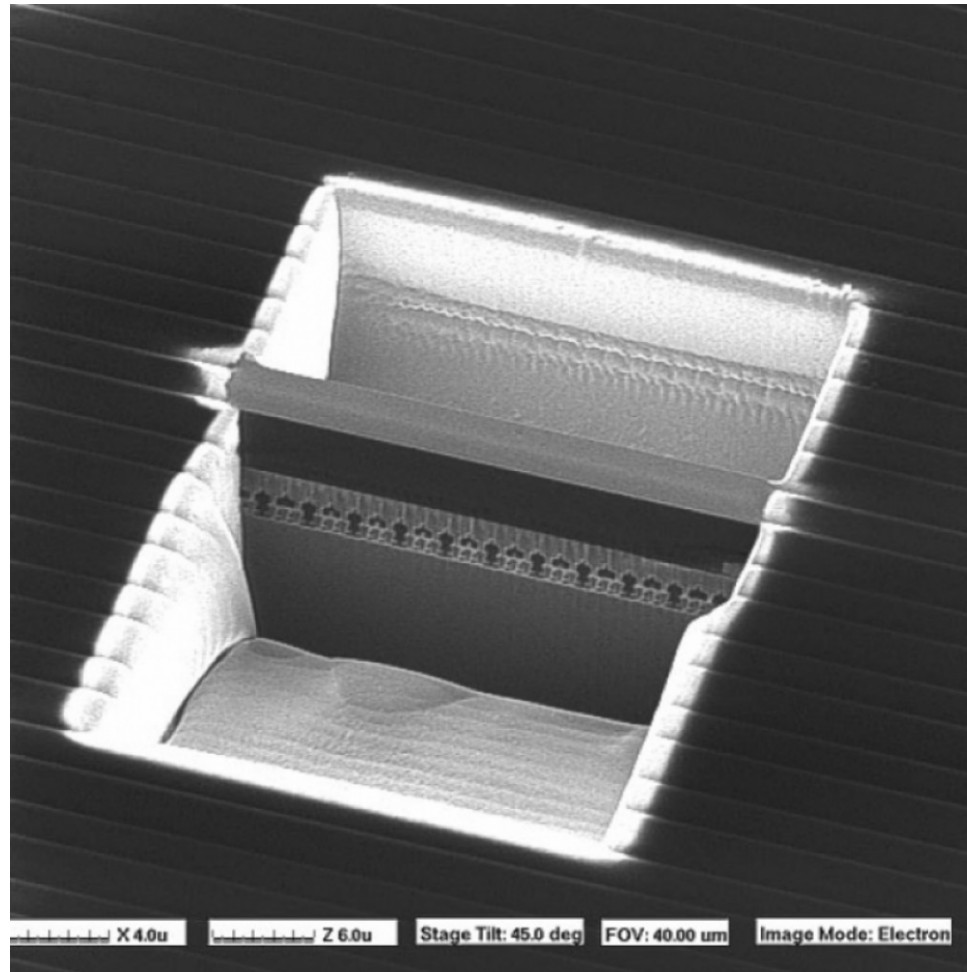
Mill Trenches around area



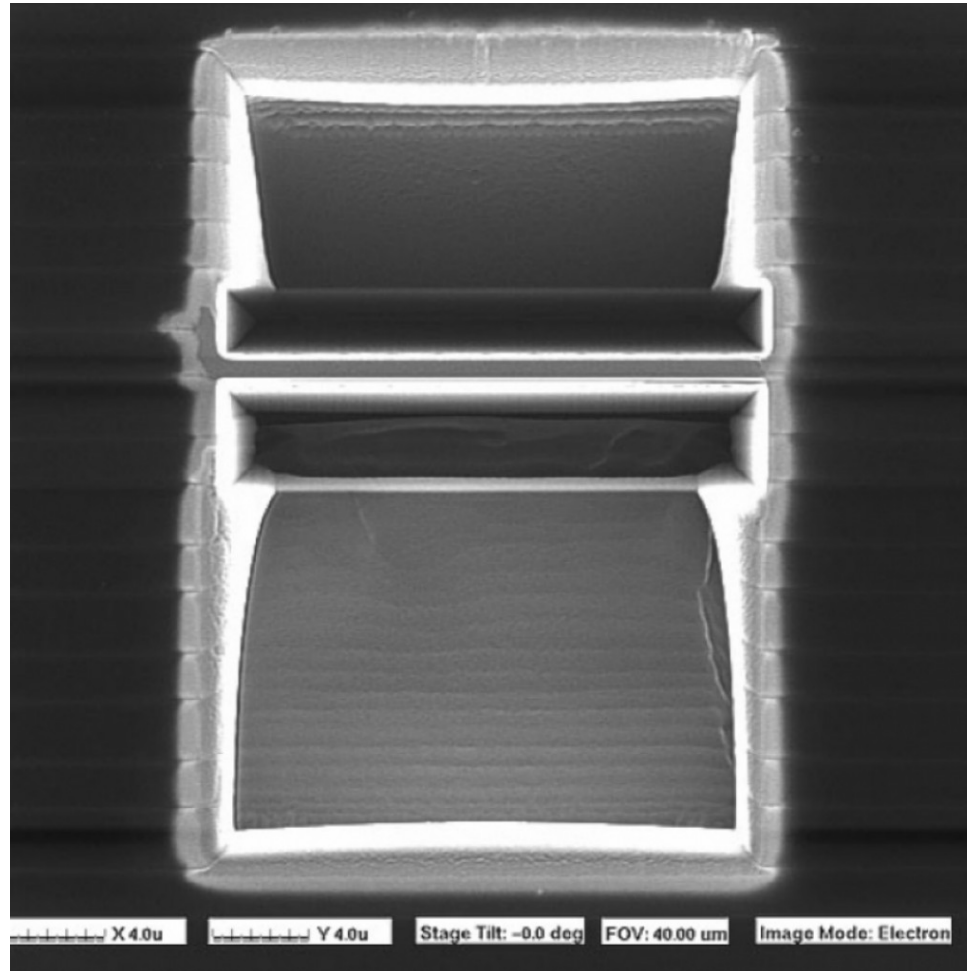
Top View of Trench



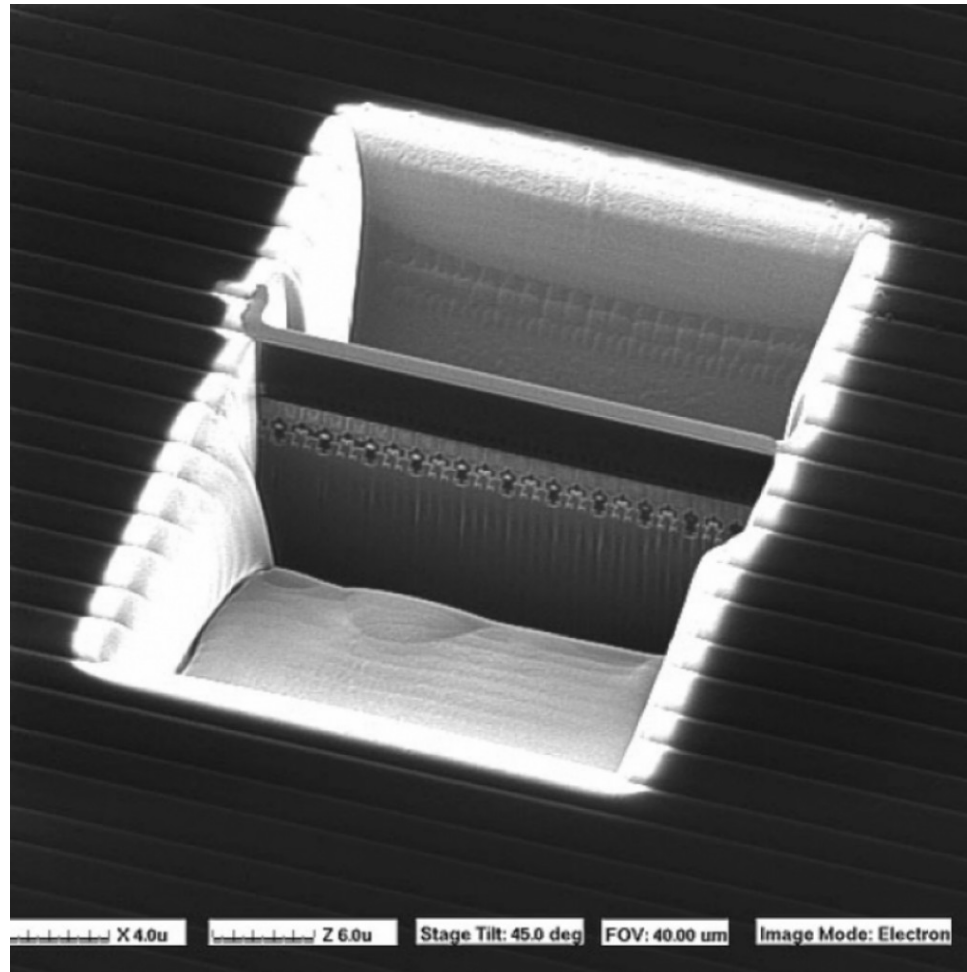
Polish Section



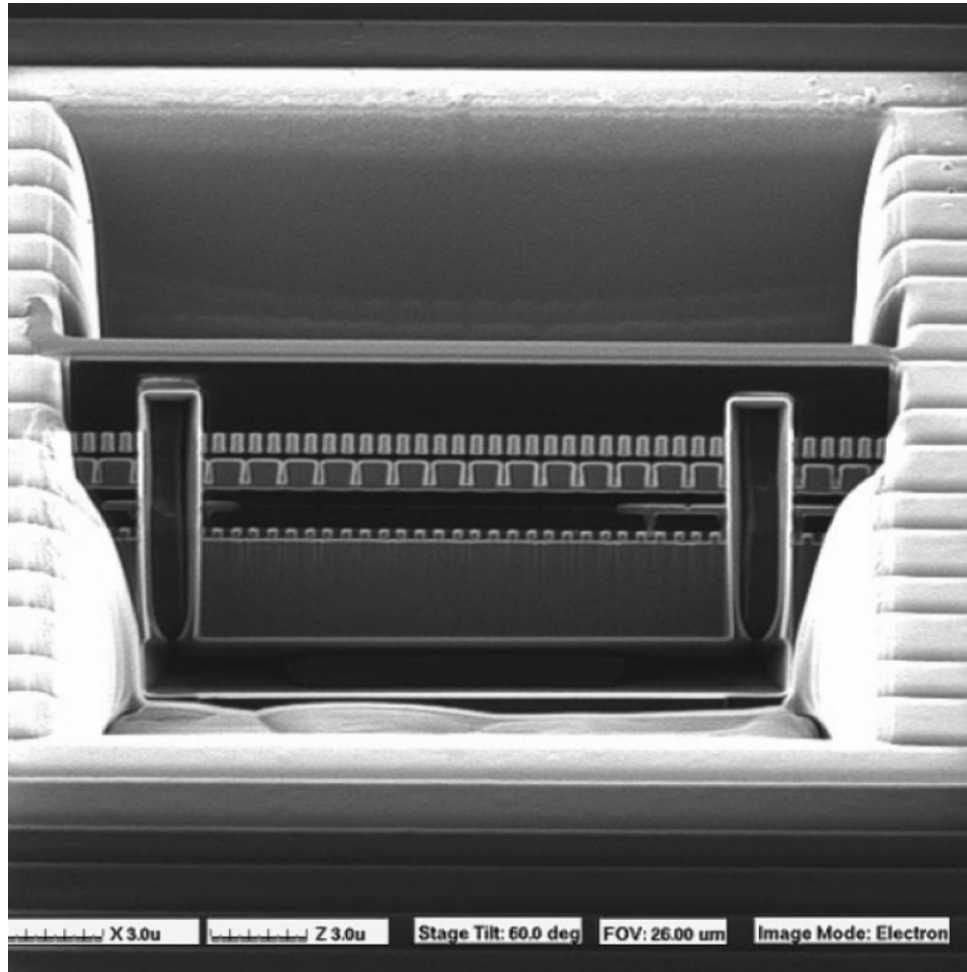
Further Polishing



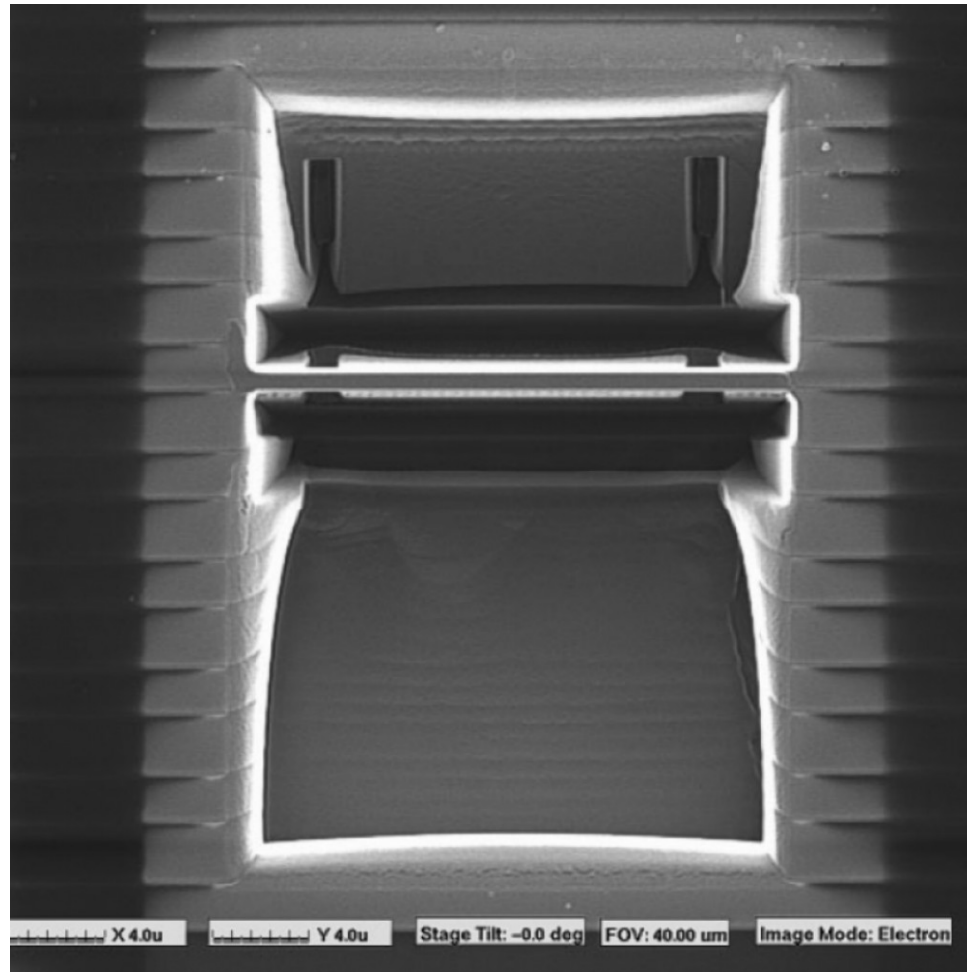
Iso-View of Second Polish



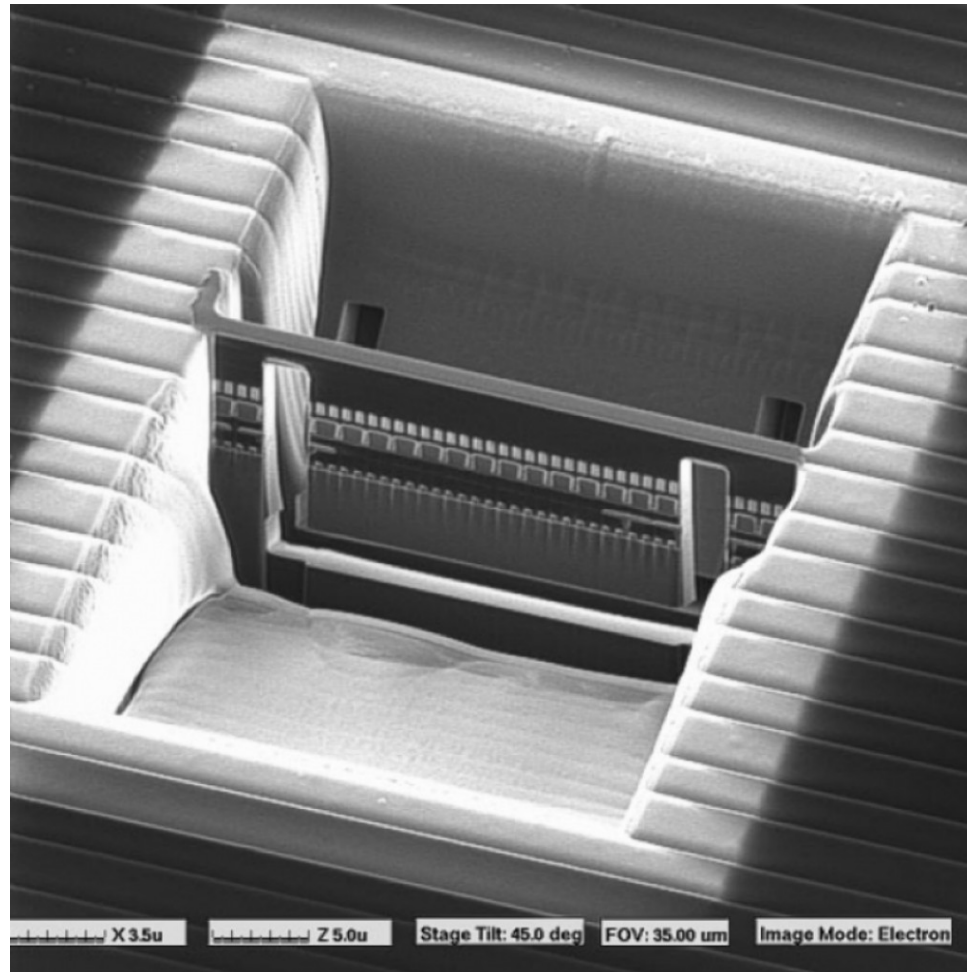
Frame Cuts to Define Area for Removal



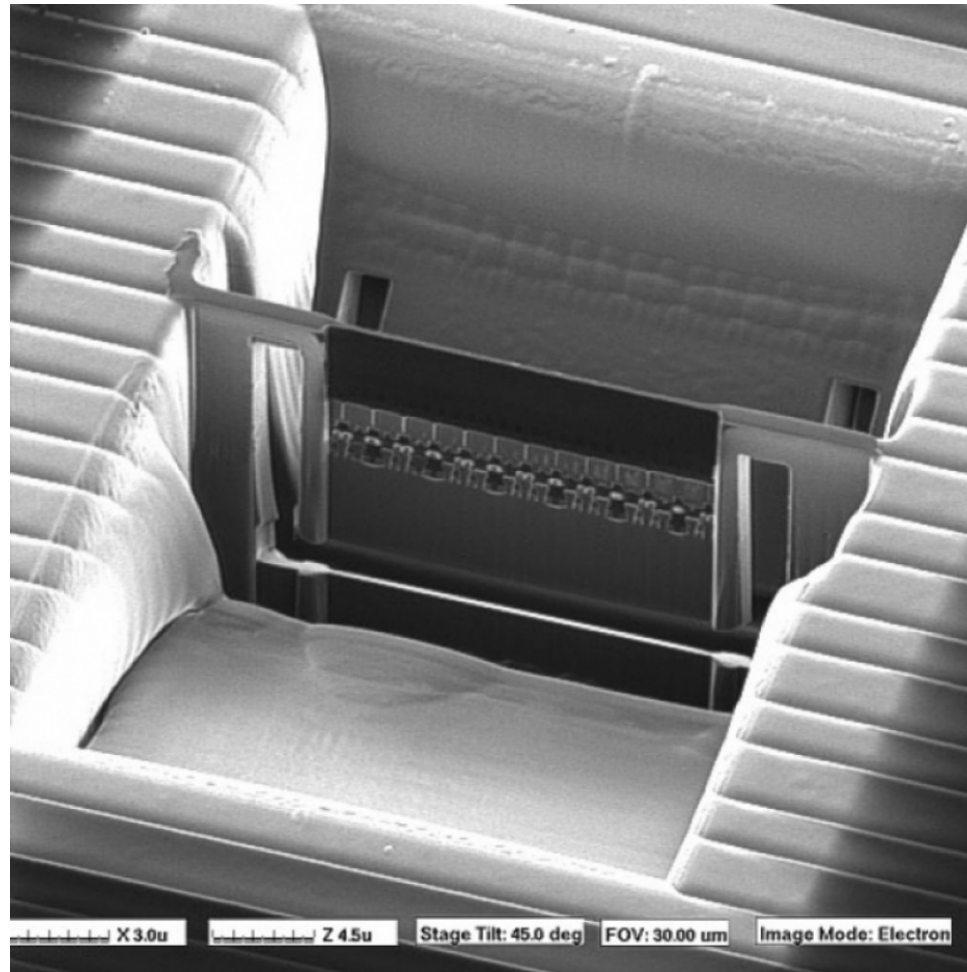
Top View of Frame Cut



Iso-View of Frame Cut



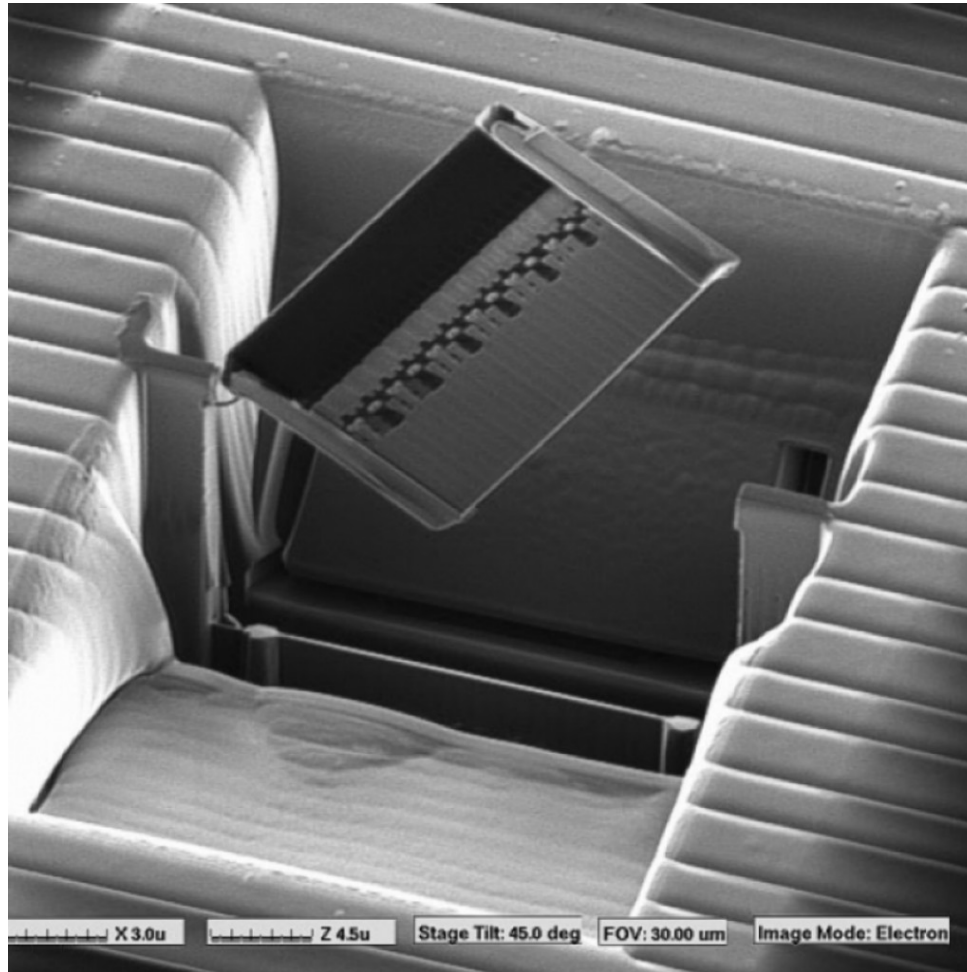
Thin to Electron Transparency



Top View just before Removal



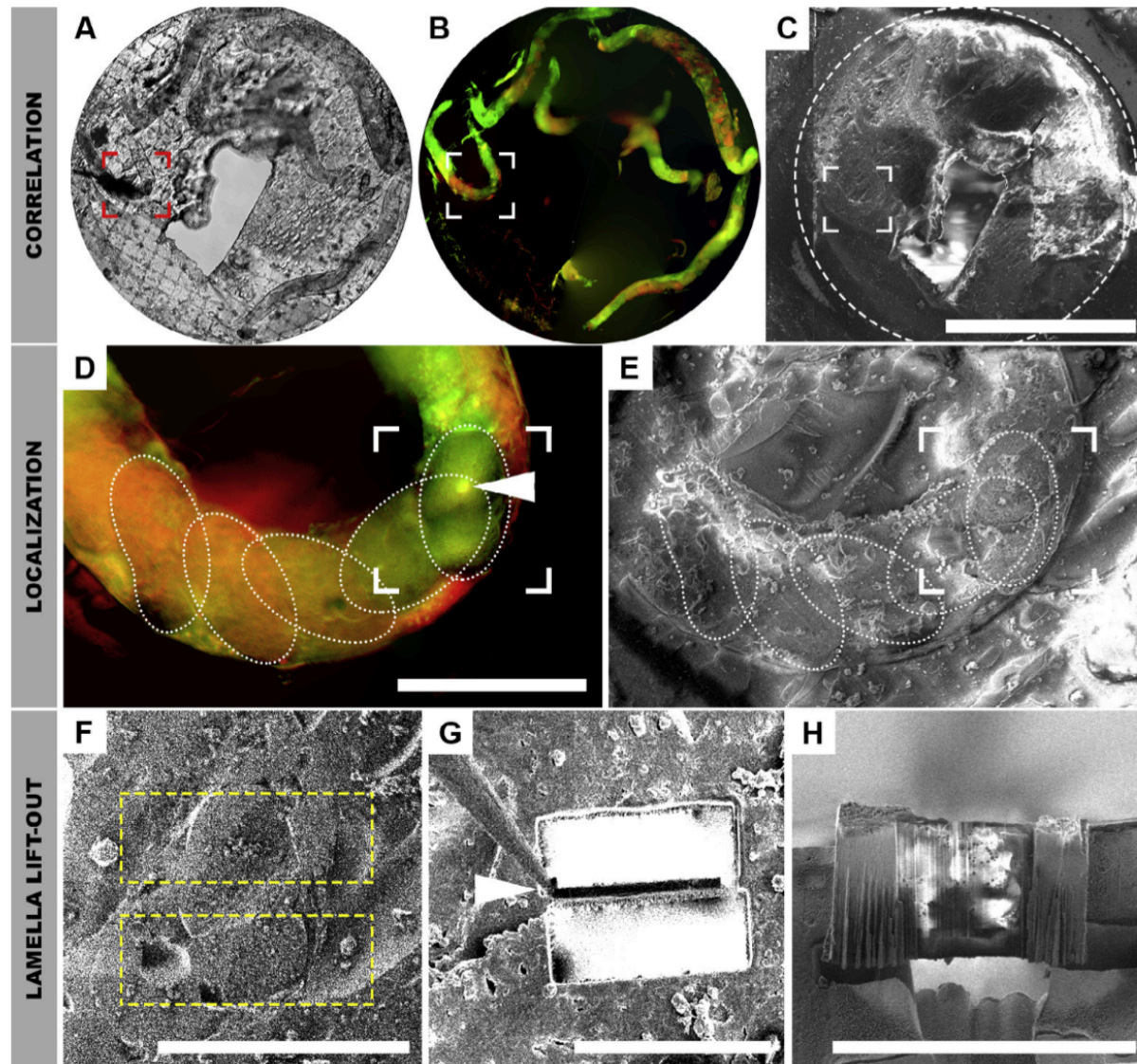
Remove Section and attach to manipulator (not shown)



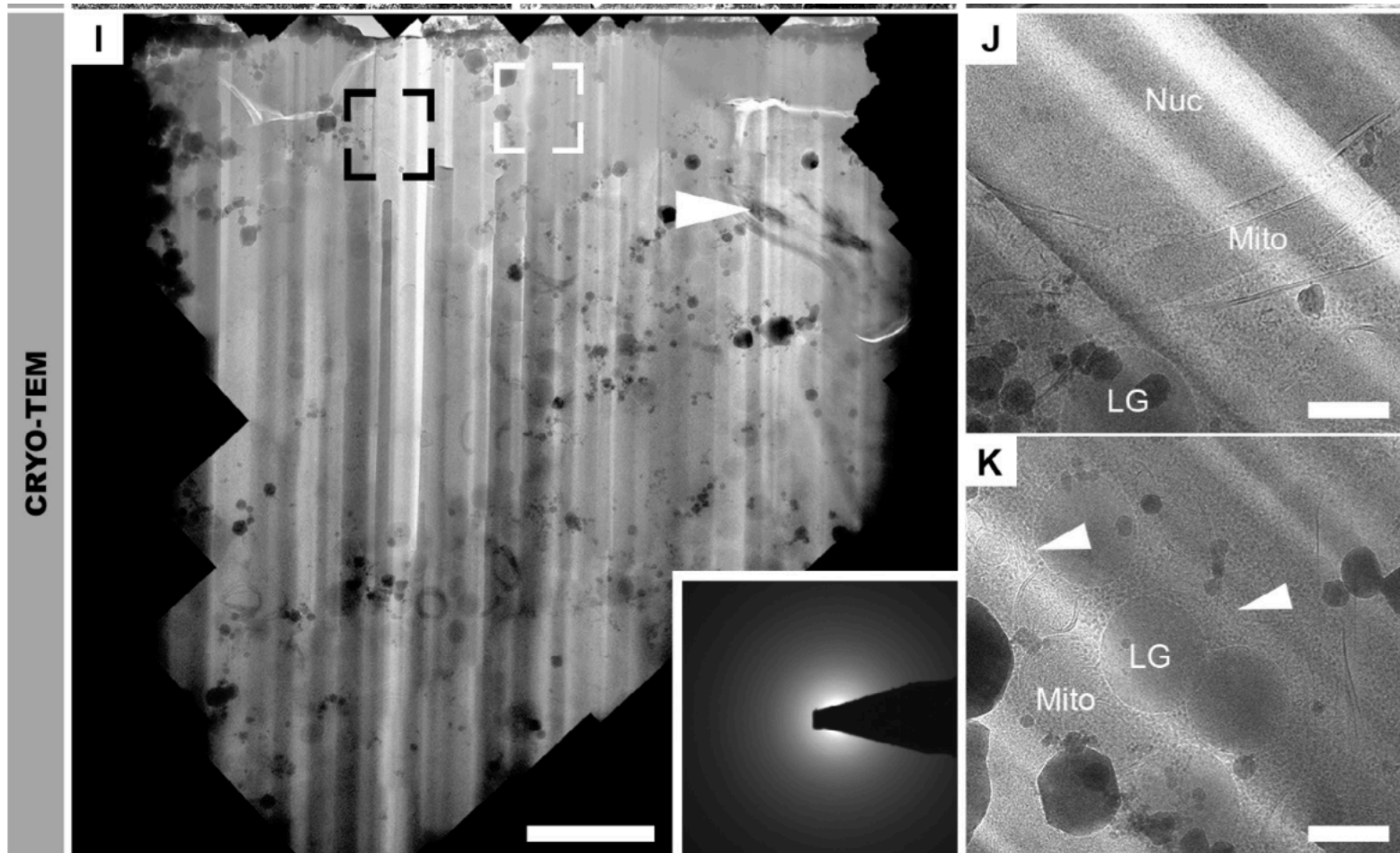
Applications to Cryo

- Mahamid J, Schampers R, Persoon H, Hyman AA, Baumeister W, Plitzko JM. A focused ion beam milling and lift-out approach for site-specific preparation of frozen-hydrated lamellas from multicellular organisms. *J Struct Biol.* 2015 Nov;192(2):262-9. doi: 10.1016/j.jsb.2015.07.012. PubMed PMID: 26216184.

C ELEGANS Embryo HPF on grid



TEM



Equipment Needed

